

Mercury+ XU8 SoC Module

User Manual

Purpose

The purpose of this document is to present the characteristics of the Mercury+ XU8 SoC module to the user, and to provide the user with a comprehensive guide to understanding and using the Mercury+ XU8 SoC module.

Summary

This document first gives an overview of the Mercury+ XU8 SoC module followed by a detailed description of its features and configuration options. In addition, references to other useful documents are included.

Product Information	Code	Name
Product	ME-XU8	Mercury+ XU8 SoC Module

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Approval Information	Name	Position	Date
Written by	DIUN, MMOS	Design Engineer	03-Sep-2018
Verified by	GKOE, RPAU	Design Expert	10-Sep-2018
Approved by	IJOS	Manager, BU-SP	10-Jul-2026

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Document History

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06	18-Nov-2019	MMOS	Added article codes for revision 2.1 modules and information on PCIe PERST# signal
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Continued on next page...

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1 Overview

1.1 General

1.1.1 Introduction

The Mercury+ XU8 SoC module combines the AMD Zynq® UltraScale+ MPSoC (Multiprocessor System-on-Chip) device with USB 3.0, PCIe® Gen3 ×16, PCIe® Gen2 ×4, two USB 2.0 PHYs, two Gigabit Ethernet PHYs, DDR4 SDRAM with Error Correction Code (ECC), eMMC flash, multi-gigabit transceivers, high-speed LVDS I/O, and is available in industrial temperature range, forming a complete and powerful embedded processing system.

The use of the Mercury+ XU8 SoC module, in contrast to building a custom MPSoC hardware, significantly reduces development effort and redesign risk and improves time-to-market for the embedded system.

Together with Mercury+ base boards, the Mercury+ XU8 SoC module allows the user to quickly build a system prototype and start with application development.

1.1.2 Warranty

Refer to the General Business Conditions, available on the Enclustra website [1].

Tip

The warranty of Enclustra modules is void if the FPGA's one-time programmable eFuses are blown. This operation is irreversible. Enclustra cannot test the module in case of a product return.

NOTICE



Data loss or unusable product

The fuses of the FPGA can be blown to activate the user-defined Advanced Encryption Standard (AES). After blowing the fuses, only content encrypted using a specific key can be loaded on the FPGA. Your key is unique and cannot be retrieved in case of loss.

- Keep your key in a secure location.

1.1.3 RoHS

The Mercury+ XU8 SoC module is designed and produced according to the Restriction of Hazardous Substances (RoHS) Directives 2011/65/EU (RoHS 2) and 2015/863/EU (RoHS 3).

1.1.4 Disposal and WEEE

The Mercury+ XU8 SoC module must be properly disposed of at the end of its life.

The Mercury+ XU8 SoC module is not subject to the Waste Electrical and Electronic Equipment (WEEE) Directive (2012/19/EU).

1.1.5 Safety Recommendations and Warnings

Mercury+ modules are not designed to be "ready for operation" for the end-user. These can only be used in combination with suitable base boards. Proper configuration of the hardware before usage is required.

NOTICE



Damage by inserting or removing the module while under power

- Ensure that the power supply is disconnected from the base board before inserting/removing the Mercury+ XU8 SoC module, connecting/disconnecting interfaces, or connecting/disconnecting jumpers.

NOTICE



Damage by touching while under power

Touching the capacitors of the DC-DC converters can lead to voltage peaks and permanent damage.

- Do not touch the capacitors of the DC-DC converters while the power is applied.

1.1.6 Electrostatic Discharge

Electronic boards are sensitive to electrostatic discharge (ESD).

NOTICE



Damage due to electrostatic discharge

Electrostatic discharge (ESD) may damage the Mercury+ XU8 SoC module partially or completely.

- Follow the relevant guidelines for ESD-safe handling when operating or assembling electronic components.
- Ensure that the product is handled with care and only in an ESD-protected environment.

1.1.7 Electromagnetic Compatibility

The Mercury+ XU8 SoC module is a Class A product (as defined in IEC 61000-3-2 standard) and is not intended for use in domestic environments. The product may cause electromagnetic interference, for which appropriate measures must be taken.

1.2 Features

- AMD Zynq® UltraScale+™ MPSoC
 - XCZU4CG/XCZU5EV/XCZU7EV/XCZU7EG device
 - FBVB900 package
 - Dual-core ARM® Cortex™-A53 MPCore™ up to 1.333 GHz (CG variants)
 - Quad-core ARM® Cortex™-A53 MPCore™ up to 1.5 GHz (EG and EV variants)
 - Dual-core ARM® Cortex™-R5 MPCore™ up to 533 MHz
 - Mali-400 MP2 GPU (EG and EV variants)
 - H.264 / H.265 Video Codec (EV variants)
 - AMD 16nm FinFET+ FPGA fabric
 - 14 ARM peripheral I/Os (SPI, SDIO, CAN, I2C, UART)
 - 122 FPGA I/Os
 - 74 HP I/Os

- 50 I/Os up to 1.8 V
 - 20 I/Os at 1.2 V (fixed voltage)
 - 4 I/Os up to 3.3 V (routed via level shifters)
- 48 HD I/Os (up to 3.3 V)
- 20 MGT transceivers
 - 16 GTH transceivers
 - Speed grade 1: 12.5 Gbit/s
 - Other devices: 15 Gbit/s
 - 4 GTR transceivers @ 6 Gbit/s
- 12 reference clock inputs
 - 8 GTH reference clock inputs
 - 4 GTR reference clock inputs
- PCIe Gen3 ×16 (AMD built-in PCIe integrated block using GTH lanes)
- PCIe Gen2 ×4 (AMD built-in PCIe hard block using GTR lanes)
- Up to 4 GB DDR4 SDRAM with ECC on PS side
- Up to 2 GB DDR4 SDRAM on PL side
- 64 MB quad SPI flash
- 16 GB eMMC flash
- 2 × Gigabit Ethernet PHY (one PHY shared with one of the USB PHYs)
- 2 × USB 2.0 PHYs
 - PHY0 configured as host or device
 - PHY1 configured as host (shared with one of the Gigabit Ethernet PHYs)
- USB 3.0 (AMD built-in USB 3.0 hard block using GTR lanes)
- CAN, UART, SPI, I2C, SDIO/MMC
- Real-time clock
- Form factor: 74 × 54 mm
- 5 to 15 V supply voltage

1.3 Deliverables

- Mercury+ XU8 SoC module
- Mercury+ XU8 SoC module documentation, available via download:
 - Mercury+ XU8 SoC Module User Manual (this document)
 - Mercury+ XU8 SoC Module Reference Design [2]
 - Mercury+ XU8 SoC Module IO Net Length Excel Sheet [3]
 - Mercury+ XU8 SoC Module FPGA Pinout Excel Sheet [4]
 - Mercury+ XU8 SoC Module User Schematic (PDF) [5]
 - Mercury+ XU8 SoC Module Known Issues and Changes [6]
 - Mercury+ XU8 SoC Module Footprint (Altium, Eagle, Orcad and PADS) [7]
 - Mercury+ XU8 SoC Module 3D Model (PDF) [8]
 - Mercury+ XU8 SoC Module 3D Model (STEP) [9]
 - Mercury Mars Module Pin Connection Guidelines [10]
 - Mercury Master Pinout [11]
 - Mercury Heat Sink Kits User Manual [21]
- Additional resources, available online:
 - Enclustra Build Environment [16] (Linux build environment; refer to Section 1.3.2 for details)
 - Enclustra Build Environment How-To Guide [17]
 - Petalinux BSP and Documentation [18]
 - Enclustra I2C Application Note [22]
 - Enclustra Gigabit Ethernet Application Note [23]
 - Enclustra ZynqMP Video Application Note [24]
 - Enclustra Secure Boot Reference Design for Zynq Ultrascale+ MPSoC [25]

1.3.1 Reference Design

The Mercury+ XU8 SoC Module Reference Design [2] features an example configuration for the Zynq UltraScale+ MPSoC device, together with an example top level HDL file for the user logic.

A bare metal “hello world” application is provided in the reference design. The example shows how to initialize the peripheral controllers and how to access the external devices. Pre-compiled binaries are included in the archive, so that the user can easily check that the hardware is functional.

Tip

To get notified about updates to the Mercury+ XU8 SoC Module Reference Design, turn on the notifications from the Enclustra GitHub page [2].

1.3.2 Enclustra Build Environment

The Enclustra Build Environment is deprecated. The latest release of the reference design is compatible with AMD tools release 2022.1.

The Enclustra Build Environment (EBE) [16] enables the user to quickly set up and run Linux on any Enclustra SoC module or system board. It allows the user to choose the desired target, and download all the required binaries, such as bitstream and FSBL. It downloads and compiles all required software, such as U-Boot, Linux, and BusyBox based root file system.

The Enclustra Build Environment features a graphical user interface (GUI) and a command line interface (CLI) that facilitates the automatic build flow.

The Enclustra Build Environment How-To Guide [17] describes in more detail how to use the EBE to customize the provided software for the user application. The document provides information on the configuration options for U-Boot, Linux kernel and Buildroot, debugging possibilities for Linux applications, customization of device trees and integration of existing or new kernel drivers.

1.3.3 Petalinux BSP

The Enclustra Petalinux BSP is deprecated. For reference design releases starting at 2024.2, the Enclustra Yocto BSP layer is provided instead (see Section 1.3.4).

The Enclustra Petalinux BSPs enable the user to quickly set up a Petalinux project and to run Linux on the Enclustra SoC module or system board.

The documentation [18] describes the build process in detail and allows a user without Petalinux knowledge to build and run the desired design on the target hardware.

1.3.4 Yocto BSP Layer

The Enclustra Yocto BSP layer enables the user to quickly set up a Yocto project and to run Linux on the Enclustra SoC module.

The documentation [19] describes the build process in detail and allows a user without Yocto knowledge to build and run a Linux reference design on the target hardware.

1.4 Accessories

1.4.1 Enclustra Heat Sink

For Mercury modules an Enclustra heat sink is available for purchase along with the product. Refer to Section 3.10.6 for further information on the available cooling options.

1.4.2 Mercury+ PE1 Base Board

The Mercury+ PE1 [13] is a versatile PCIe® x4 base board equipped with a multitude of I/O interfaces for use with the Mercury/Mercury+ family of FPGA and SoC modules, providing a head start for building custom FPGA- and SoC-based hardware systems.

It is compatible with a multitude of FMC boards from different suppliers to use in data acquisition systems, motor control, display and camera interfaces, software defined radio and more. The board is equally well suited for rapid prototyping and for building FPGA systems without designing custom hardware.

The available features depend on the Mercury module type and on the selected base board variant.

Tip

The pinout assignments (pin types and I/O voltage levels) on the module connectors B and C affects the FMC interfaces. The compatibility of the Mercury+ XU8 SoC module with the Mercury+ PE1 base board is therefore limited. Compare the FMC module pinout in detail with the Enclustra Mercury Master Pinout and with the module and base board schematic.

1.4.3 Mercury+ PE3 Base Board

The Mercury+ PE3 [15] is a versatile PCIe® x8 base board equipped with a multitude of I/O interfaces for use with the Mercury/Mercury+ family of FPGA and SoC modules, providing a head start for building custom FPGA- and SoC-based hardware systems.

This high performance base board provides a versatile set of I/O connectivity options, specialized for high-speed communication and video applications, including SFP+, QSFP+, HDMI, USB Type-C and Firefly. The board is equally well suited for rapid prototyping and for building FPGA systems without designing custom hardware.

The available features depend on the Mercury module type and on the selected base board variant.

1.4.4 Mercury+ ST1 Base Board

The Mercury+ ST1 board [14] is a compact, low-cost base board equipped with a multitude of I/O interfaces for use with the Mercury/Mercury+ family of FPGA and SoC modules.

It provides a versatile set of I/O connectivity options, specialized for video applications, including DisplayPort, HDMI, MIPI, and SFP+. The board is equally well suited for rapid prototyping and for building FPGA systems without designing custom hardware.

The available features depend on the Mercury module type and on the selected base board variant.

1.5 AMD Tool Support

The MPSoC devices assembled on the Mercury+ XU8 SoC module are supported by the Vivado ML Standard Edition software, which is available free of charge. Contact AMD for further information.

2 Getting Started

This section contains essential information on using the Mercury+ XU8 SoC module.

NOTICE



Damage to the connectors

The connectors of the module and the base board can be damaged if the connectors are not properly aligned during installation.

- Align the connectors carefully before applying force on the module.
- Do not use excessive force to latch the module into the connectors on the base board.

NOTICE



Damage to the device when applying power

The Mercury module could physically be mounted the wrong way around on the base board. The module and the base board can be damaged if the device is powered on while it is connected the wrong way around.

- Ensure that the mounting holes on the base board are aligned with the mounting holes of the module.

NOTICE



Damage to the module by overtightening screws

- Do not use excessive force when tightening the screws.

NOTICE



Damage to the device by using metallic objects for removal

- Do not use metallic object, such as screwdrivers, to remove the module from the base board.
- Remove the module carefully using your fingers to avoid damage.
- If more force is required, always apply it evenly by hand to avoid damage.

2.1 Installing the Module

Tip

A small copper square on the bottom left corner of Enclustra modules is provided as landmark. The same landmark is provided on the Enclustra base boards to help orient the module in the right direction when connecting it.

1. **NOTICE: Damage due to electrostatic discharge (ESD).**
Ensure that the product is handled in an ESD-protected environment.
2. **NOTICE: Damage by connecting or disconnecting under power.**
Ensure that the power of the base board is disconnected.
3. **NOTICE: Damage to the device when applying power. The module could physically be mounted the wrong way around on the base board.**
Identify the correct orientation and position of the module with respect to the base board.
4. **NOTICE: Damage to the connectors. Align the connectors carefully before applying force on the module. Do not use excessive force to latch the module into the connectors on the base board.**
Align the connectors and press the module onto the base board.
5. **NOTICE: Damage to the module. Do not use excessive force when tightening the screws.**
If required, use up to four M3 screws to mechanically fasten the module to the base board.

2.2 Removing the Module

1. **NOTICE: Damage due to electrostatic discharge (ESD).**
Ensure that the product is handled in an ESD-protected environment.
2. **NOTICE: Damage by connecting or disconnecting under power.**
Ensure that the power of the base board is disconnected.
3. **NOTICE: Damage to the device. Do not use any metallic object to remove the module from the base board.**
Remove the module carefully using your fingers.

3 Module Description

3.1 Block Diagram

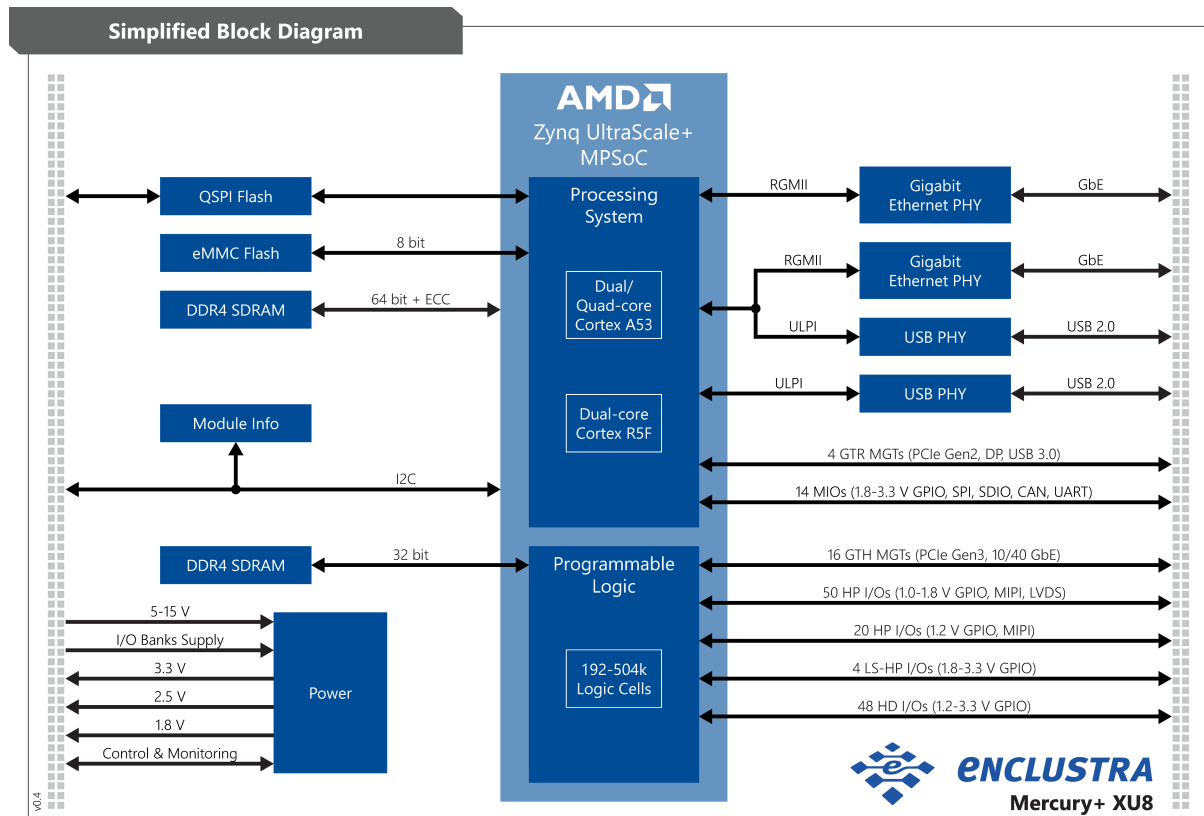


Figure 1: Hardware Block Diagram

The main component of the Mercury+ XU8 SoC module is the AMD Zynq UltraScale+ MPSoC device. Most of its I/O pins are connected to the Mercury+ module connector, making 136 regular user I/Os available to the user. Further, twenty MGT pairs are available on the module connector, making possible the implementation of several high-speed protocols such as PCIe Gen3 $\times$ 16, PCIe Gen2 $\times$ 4 and USB 3.0 (simultaneous usage of all the interfaces is limited to the available hardware resources i.e. number of transceivers and lane mapping).

The MPSoC device can boot from the on-board QSPI flash, from the eMMC flash or from an external SD card. For development purposes, a JTAG interface is connected to Mercury module connector.

The available standard configurations include a 16 GB eMMC flash, a 64 MB quad SPI flash, up to 4 GB DDR4 SDRAM with ECC connected to the Processing System (PS) and up to 2 GB DDR4 SDRAM connected to the Programmable Logic (PL).

Further, the module is equipped with two Gigabit Ethernet PHYs and two USB 2.0 PHYs, making it ideal for communication applications.

A real-time clock is available on the AMD Zynq UltraScale+ MPSoC device.

PS on-module clock generation is based on a 33.33 MHz oscillator. Two 100 MHz LVDS oscillators provide a clock for the PL and a reference clock for the MGT GTR transceivers. In addition, a 27 MHz oscillator

delivers a reference clock for the MGT GTR transceivers.

The module's internal supply voltages are generated from a single input supply of 5 to 15 V DC. Some of these voltages are available on the Mercury module connectors to supply circuits on the base board.

Five LEDs are connected to the MPSoC pins for status signaling.

3.2 Module Configuration and Product Models

Table 1 describes the available standard module configurations. The product model indicates the module type and main features. Figure 2 describes the fields within the product model. Custom configurations are available. Contact Enclustra for more information.

Product Model	MPSoC ¹	DDR4 ECC SDRAM (PS)	DDR4 SDRAM (PL)	Temperature Range
ME-XU8-4CG-1I-D11E	XC ZU4 CG-1FBVB900I	2 GB	1 GB	-40 to +85°C
ME-XU8-5EV-1I-D12E	XC ZU5 EV-1FBVB900I	4 GB	2 GB	-40 to +85°C
ME-XU8-5EV-1I-D12E-NE ²	XC ZU5 EV-1FBVB900I	4 GB	2 GB	-40 to +85°C
ME-XU8-7EG-2I-D11E ²	XC ZU7 EG-2FBVB900I	2 GB	1 GB	-40 to +85°C
ME-XU8-7EV-2I-D12E	XC ZU7 EV-2FBVB900I	4 GB	2 GB	-40 to +85°C
ME-XU8-7EV-2I-D12E-E1 ²	XC ZU7 EV-2FBVB900I	4 GB	2 GB	-40 to +85°C
ME-XU8-7EV-2E-D13E ²	XC ZU7 EV-2FBVB900I	8 GB	4 GB	0 to +85°C

Table 1: Standard Module Configurations

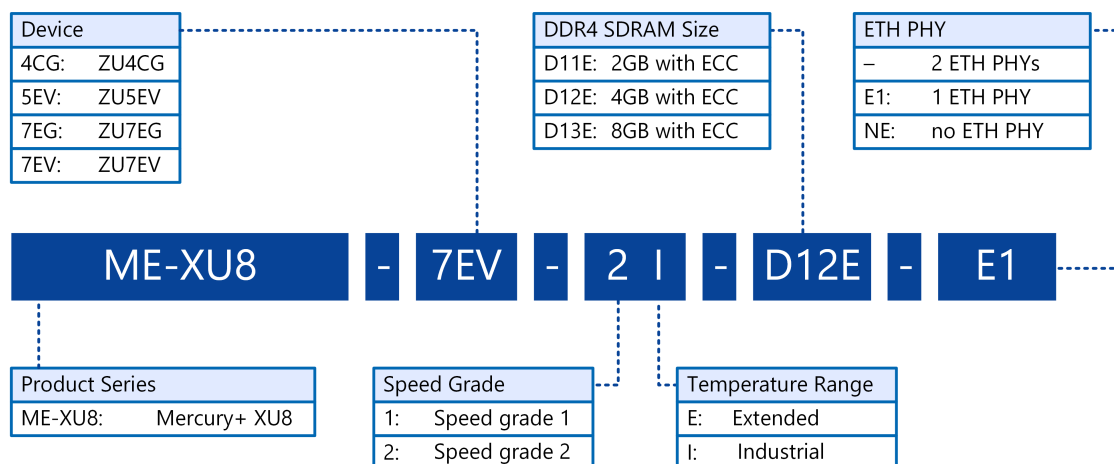


Figure 2: Product Model Fields

For the first revision modules or early access modules, the product model may not respect entirely this naming convention. Contact Enclustra for more information.

¹The "device" is shown in bold.

²This product model is no longer available as standard product.

3.3 EN-Numbers and Product Models

Every product is uniquely labeled, showing the EN-number and serial number. An example is presented in Figure 3.

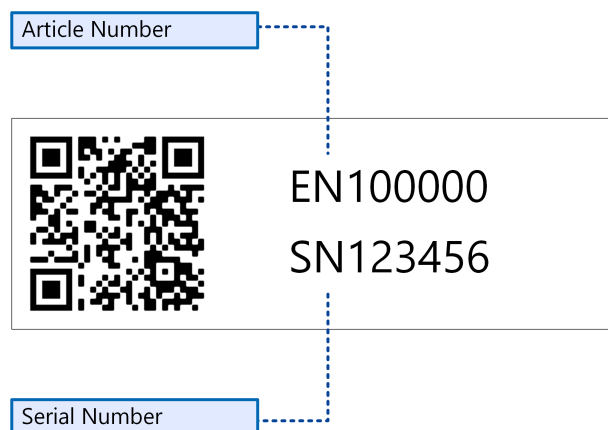


Figure 3: Product Label

The correspondence between EN-number and product model for each revision is shown in Table 2.

The known issues of the product and the changes between the revisions are described in the Mercury+ XU8 SoC Module Known Issues and Changes [6].

EN-Number	Product Model	Product Revision
EN105198	ME-XU8-7EV-2I-D12E	R2.2
EN105196	ME-XU8-7EV-1E-D11E	R2.2
EN105195	ME-XU8-5EV-1I-D12E	R2.2
EN105187	ME-XU8-4CG-1I-D11E	R2.2
EN105185	ME-XU8-4CG-1E-D11E	R2.2
EN105067	ME-XU8-7EV-2E-D13E	R3.0
EN104509	ME-XU8-7EG-2I-D11E	R3.0
EN104467	ME-XU8-5EV-1I-D12E-NE	R3.0
EN104466	ME-XU8-7EV-2I-D12E-E1	R3.0
EN104465	ME-XU8-7EV-2I-D12E	R3.0
EN104464	ME-XU8-7EV-1E-D11E	R3.0
EN104463	ME-XU8-5EV-1I-D12E	R3.0
EN104462	ME-XU8-4CG-1I-D11E	R3.0

Continued on next page...

EN-Number	Product Model	Product Revision
EN104461	ME-XU8-4CG-1E-D11E	R3.0
EN102720	ME-XU8-4CG-1I-D11E	R2.1
EN102676	ME-XU8-7EV-1E-D11E	R2.1
EN102675	ME-XU8-7EV-2I-D12E	R2.1
EN102674	ME-XU8-5EV-1I-D12E	R2.1
EN102673	ME-XU8-4CG-1E-D11E	R2.1
EN102605	ME-XU8-7EV-1E-D11E	R2.0
EN102342	ME-XU8-7EV-2I-D12E	R2.0
EN102341	ME-XU8-5EV-1I-D12E	R2.0
EN102340	ME-XU8-4CG-1E-D11E	R2.0
EN102312	ME-XU8-7EV-2I-D12E	R1.1
EN102311	ME-XU8-5EV-1I-D12E	R1.1
EN102310	ME-XU8-4CG-1E-D11E	R1.1
EN102157	ME-XU8-7EV-2I-D12E	R1.0
EN102156	ME-XU8-5EV-1I-D12E	R1.0
EN102155	ME-XU8-4CG-1E-D11E	R1.0

Table 2: EN-Numbers and Product Models

3.4 Top and Bottom Views

Depending on the hardware revision and configuration, the module may look slightly different than shown in this document.

3.4.1 Top View

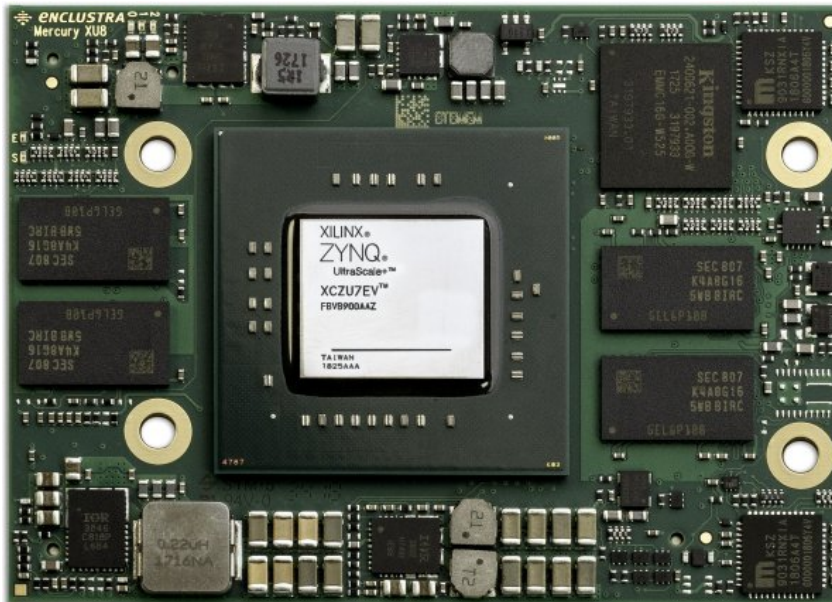


Figure 4: Module Top View

3.4.2 Bottom View

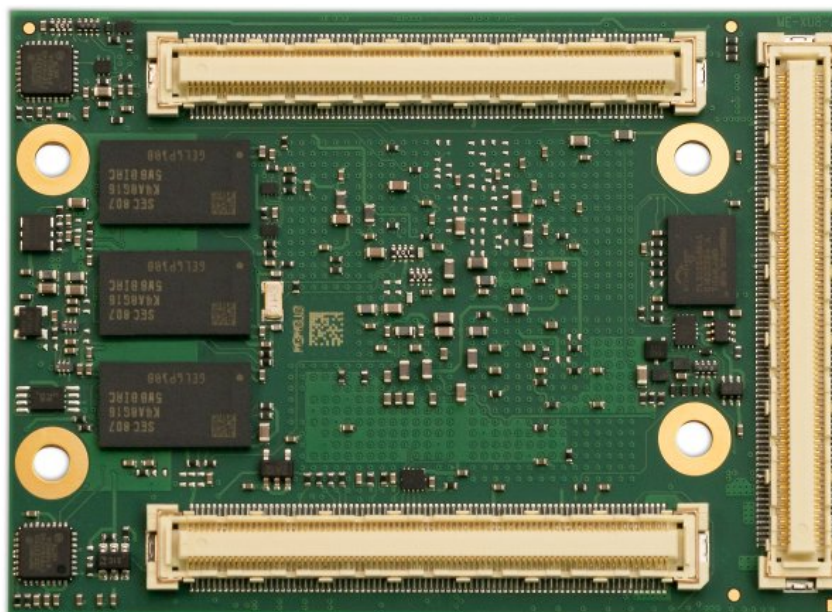


Figure 5: Module Bottom View

3.5 Top and Bottom Assembly Drawings

Depending on the hardware revision and configuration, the module may look slightly different than shown in this document.

3.5.1 Top Assembly Drawing

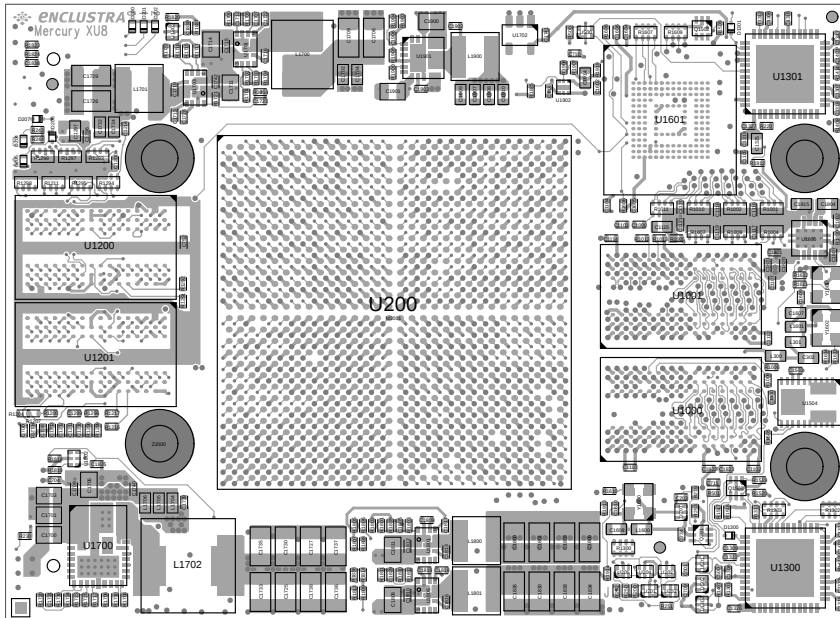


Figure 6: Module Top Assembly Drawing

3.5.2 Bottom Assembly Drawing

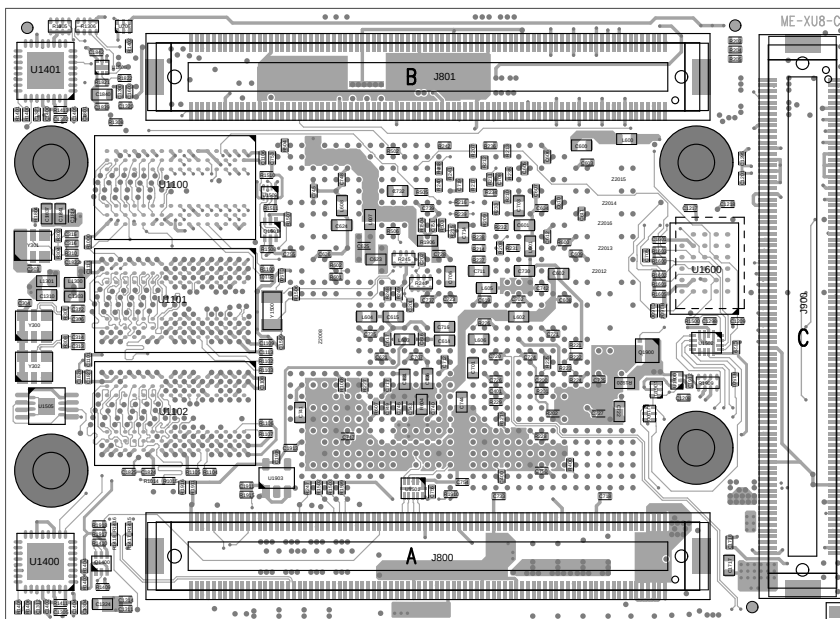


Figure 7: Module Bottom Assembly Drawing

3.6 Module Footprint and Mechanical Data

Figure 8 shows the dimensions of the module footprint on the base board.

Enclustra offers Mercury and Mercury+ modules of various geometries having widths of 56, 64, 65, 72 or 74 mm and having different topologies for the mounting holes. If different module types shall be fixed on the base board by screws, additional mounting holes may be required to accommodate different modules. The footprints of the module connectors for the base board design are available for different PCB design tools (Altium, PADS, Eagle, Orcad) [7] and include the required information on the module sizes and holes.

The maximum component height under the module is dependent on the connector type. Refer to Section 3.7 for detailed connector information.

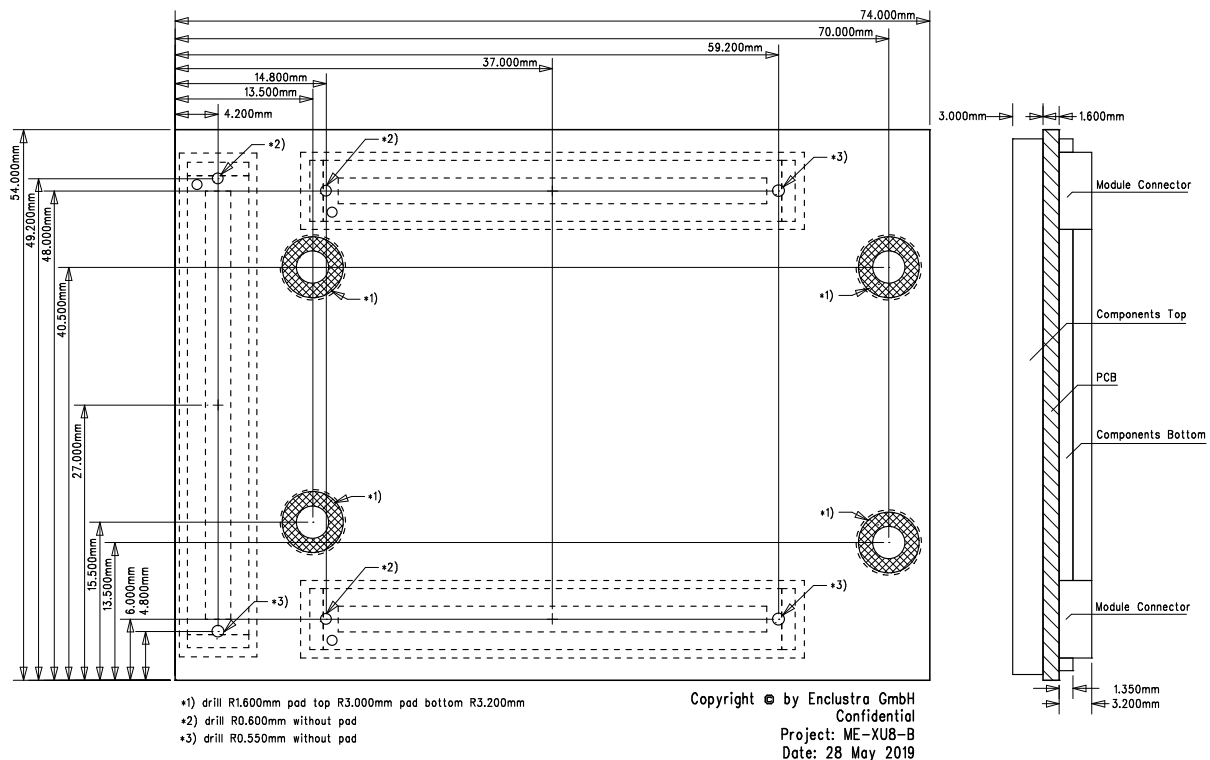


Figure 8: Module Footprint - Top View and Side View

Table 3 describes the mechanical characteristics of the Mercury+ XU8 SoC module. A 3D model (PDF) and a STEP 3D model are available [8], [9].

Parameter	Value
Size	74 × 54 mm
Component height top	3.00 mm
Component height bottom	1.35 mm
Weight	34 g

Table 3: Mechanical Data

3.7 Module Connector

Three Hirose FX10 168-pin 0.5 mm pitch headers with a total of 504 pins have to be integrated on the base board [12]. The pinout of the module connector is found in the Mercury Master Pinout [11]. The connector is available in different packaging options and different stacking heights. Some examples are presented in Table 4. Refer to the connector datasheet for more information.

Component	Part Number	Description
Mercury module connector	FX10A-168S-SV	Hirose FX10, 168-pin, 0.5 mm pitch
Base board connector	FX10A-168P-SV(71)	Hirose FX10, 168-pin, 0.5 mm pitch, 4 mm stacking height
Base board connector	FX10A-168P-SV1(71)	Hirose FX10, 168-pin, 0.5 mm pitch, 5 mm stacking height

Table 4: Module Connector Characteristics

Figure 9 indicates the pin numbering for the Mercury module connectors from the top view of the base board. The connector pins are numbered as follows:

- Connector A: from J800-1 to J800-168
- Connector B: from J801-1 to J801-168
- Connector C: from J900-1 to J900-168

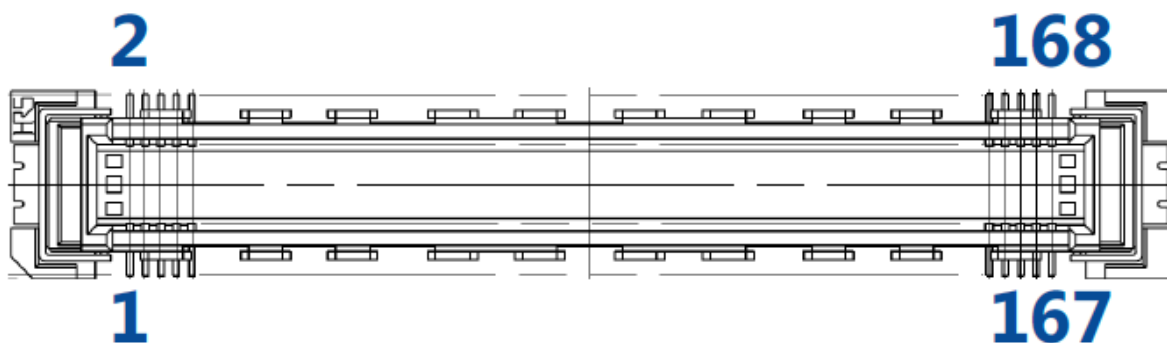


Figure 9: Pin Numbering for the Module Connector

3.8 User I/O

3.8.1 Pinout

Information on the Mercury+ XU8 SoC module pins can be found in the Mercury Master Pinout [11], and in the additional document Mercury Mars Module Pin Connection Guidelines [10].

Tip

The pin types on the schematic of the module connector and in the master pinout document are for reference only. On the Mercury+ XU8 SoC module, the connected pins might not have the targeted functions (such as primary clocks, differential pins, transceiver signals, etc).

Tip

The availability of certain pins might depend on the product model.

The naming convention for the user I/Os located in HP banks is:

IO_B<BANK>_L<PAIR>_<SPECIAL_FUNCTION>_<PACKAGE_PIN>_<POLARITY>.

For example, IO_B66_L4_AD7_AD11_P is located on pin AD11 of I/O bank 66, pair 4, it is a System Monitor differential auxiliary analog input capable pin and it has positive polarity, when used in a differential pair.

The HD banks are numbered differently depending on the MPSoC device assembled on the module. Table 5 presents the mapping between the generic bank letters and the device-specific bank numbers.

Device	Bank	
	N	O
ZU4	46	47
ZU5		
ZU7	45	48

Table 5: Mapping Between the Generic I/O Bank Letters and the Device-Specific I/O Bank Numbers

The naming convention for the user I/Os located in HD banks is:

IO_B<BANK_LETTER>_L<PAIR>_<SPECIAL_FUNCTION>_<PACKAGE_PIN>_<POLARITY>

For example, IO_BN_L7_HDGC_AD5_E13_N is located on pin E13 of I/O bank N, pair 7, it is a System Monitor differential auxiliary analog input capable pin and also a clock capable pin and it has negative polarity, when used in a differential pair.

The global clock capable pins are marked with "GC" (HP I/O banks) or with "HDGC" (HD I/O banks) in the signal name. For details on their function and usage, refer to the AMD documentation.

Table 6 includes information related to the total number of I/Os available in each I/O bank and possible limitations.

Signal Name	Sign.	Pairs	Differential	Single-ended	Bank	Bank Type ³
IO_B64_<...>	4	0	–	In/Out	64	HP
IO_B65_<...>	20	10	In/Out	In/Out	65	HP
IO_B66_<...>	50	24	In/Out	In/Out	66	HP
IO_BN_<...>	24	12	In/Out (no LVDS/LVPECL outputs supported; internal differential termination not supported) Refer to Section 3.8.3 for details.	In/Out	N	HD
IO_BO_<...>	24	12	In/Out (no LVDS/LVPECL outputs supported; internal differential termination not supported) Refer to Section 3.8.3 for details.	In/Out	O	HD
Total	122	58	–	–	–	–

Table 6: User I/Os

The multi-gigabit transceiver (MGT) are described in Section 3.9.

3.8.2 I/O Pin Exceptions

The I/O pin exceptions are pins with special functions or restrictions (for example, when used in combination with certain Mercury boards they may have a specific role).

PCIe Reset Signal (PERST#)

Table 7 lists the I/O pin exceptions on the Mercury+ XU8 SoC module related to the PCIe reset connection.

I/O Name	Module Connector Pin	Description
PS_MIO42_PERST#	A-104	Connected to ETH0_TXD3_PERST# and PL_PERST# via switches, series resistors, and a level shifter. Refer to the Mercury+ XU8 SoC Module User Schematic for details.

Table 7: I/O Pin Exceptions - PERST#

When the Mercury+ XU8 SoC module is used in combination with a Mercury+ PE1 base board as a PCIe device, the PERST# signal coming from the PCIe edge connector on the module connector pin A-104 (PS_MIO42_PERST#) is driven further to PL_PERST# and to ETH0_TXD3_PERST# (MIO30) when its value is low.

When a PCIe block on the PL side is used, the PERST# signal is connected to the MPSoC pin PL_PERST# via a 47 kΩ resistor.

³HD = high density pins, HP = high performance pins. Refer to the Zynq UltraScale+ MPSoC Data Sheet: Overview [31] for details.

When a PCIe block on the PS side is used, the PERST# signal is routed via a 1 k Ω resistor to MIO30. This is the default MIO pin used for the reset signal of the PCIe PS built-in block, therefore it was chosen for the reset implementation. The Ethernet controller 0 is disabled when the PCIe hard block is used. Any other valid position for PERST# would have resulted in having the Ethernet controller disabled.

Using a PCIe block in the PL simultaneously with Gigabit Ethernet 0 interface on the PS side is possible. Simultaneous usage of two PCIe endpoints on the PL and PS sides is not supported and was not tested on Enclustra side.

In situations in which PCIe functionality is not required, PS_MIO42_PERST# pin can be used in the same manner as a regular MIO pin.

For root complex applications the PERST# signal can be placed on any unused MIO pin (the restriction on MIO30/42 does not apply in this case).

I/O Pins with Level Shifter

There are four signals on the Mercury+ XU8 SoC module that are routed from the FPGA banks to the module connector via level shifters. These are presented in Table 8.

Signal Name	Module Connector Pin	Description
IO_B64_AF17_LS	A-88	These pins have a level shifter from VCC_1V2 to VCC_CFG_MIO
IO_B64_AC19_LS	A-90	
IO_B64_AH16_LS	A-92	
IO_B64_AG19_LS	A-94	

Table 8: I/O Pin Exceptions - Level Shifters

The level shifters used for the I/O pins mentioned in Table 8 are NXP NTB0104 and the maximum achievable data rate on these pins is 30 Mbit/s.

3.8.3 Differential I/Os

When using differential pairs, a differential impedance of 100 Ω must be matched on the base board, and the two nets of a differential pair must have the same length.

The information regarding the length of the signal lines from the MPSoC device to the module connector is available in Mercury+ XU8 SoC Module IO Net Length Excel Sheet [3]. This enables the user to match the total length of the differential pairs on the base board if required by the application.

Tip

The trace length of various signals may change between revisions of the Mercury+ XU8 SoC module. Use the information provided in the Mercury+ XU8 SoC Module IO Net Length Excel Sheet [3] to check which signals are affected. The differential signals will also be routed differentially in subsequent product revisions.

The HD bank I/Os cannot be used as LVDS/LVPECL outputs, but they can still be used as LVDS/LVPECL differential inputs.

For information about signal terminations, refer to Section 3.8.6.

3.8.4 I/O Banks

Table 9 describes the main attributes of the Programmable Logic (PL) and Processing System (PS) I/O banks, and indicates which peripherals are connected to each I/O bank. All I/O pins in a given I/O bank must use the same I/O voltage (VCC_IO) and reference voltage (VREF).

Bank	Bank Type	Connectivity	Supply Voltage	Ref. Voltage
MGT Banks				
A	MGT	Module connector	0.9 V	–
B	MGT	Module connector	0.9 V	–
C	MGT	Module connector	0.9 V	–
D	MGT	Module connector	0.9 V	–
PL I/O Banks				
64	HP	PL DDR4 SDRAM, I2C, LEDs, module connector	1.2 V	Internal
65	HP	PL DDR4 SDRAM, clock oscillator, module connector	1.2 V	Internal
66	HP	Module connector	VCC_IO_B66, user selectable	$\frac{1}{2} \times VCC_IO_B66$
N	HD	Module connector	VCC_IO_BN, user selectable	–
O	HD	Module connector	VCC_IO_BO, user selectable	–
PS Banks				
500	PS MIO	eMMC and QSPI flash devices, I2C, LEDs	1.8 V	–
501	PS MIO	Gigabit Ethernet PHY 0, module connector	VCC_CFG_MIO, user selectable	–
502	PS MIO	USB PHY 0, Gigabit Ethernet PHY 1 / USB PHY 1 (shared lines)	1.8 V	–
503	PS CONFIG	FPGA PS Configuration	VCC_CFG_MIO, user selectable	–
504	PS DDR	PS DDR4 SDRAM	1.2 V	–
505	PS GTR	Module connector, GTR oscillators	VCC_0V85	–

Table 9: I/O Banks

3.8.5 VCC_IO Usage

The VCC_IO voltages for the I/O banks located on the module connector are configurable by applying the required voltage to the VCC_IO_B[x], respectively VCC_CFG_[x] pins. All VCC_IO_B[x] or VCC_CFG_[x] pins in a given bank must be connected to the same voltage.

For compatibility with other Enclustra Mercury modules, it is recommended to use a single I/O voltage per module connector.

Signal Name	MPSoC Pins	Supported Voltages ⁴	Connector	Connector
			A Pins	B Pins
VCC_CFG_MIO	VCCO_PSIO1_501, VCCO_PSIO3_503	1.8 V – 3.3 V $\pm$ 5%	74, 77	–
VCC_IO_B66	VCCO_66	1.0 V – 1.8 V $\pm$ 5%	–	64, 67, 88, 95, 140, 143
VCC_IO_BN	VCCO_N ⁵	1.2 V – 3.3 V $\pm$ 5% ⁶	38	–
VCC_IO_BO	VCCO_O ⁵	1.2 V – 3.3 V $\pm$ 5% ⁶	41	–

Table 10: VCC_IO Pins

Figure 10 illustrates the requirements of the VCC_IO power sequence. Do not power the VCC_IO pins when PWR_GOOD and PWR_EN signals are not active. If the module is not powered, make sure that the VCC_IO voltages are disabled, for example, by using a switch that uses PWR_GOOD as enable signal on the base board.

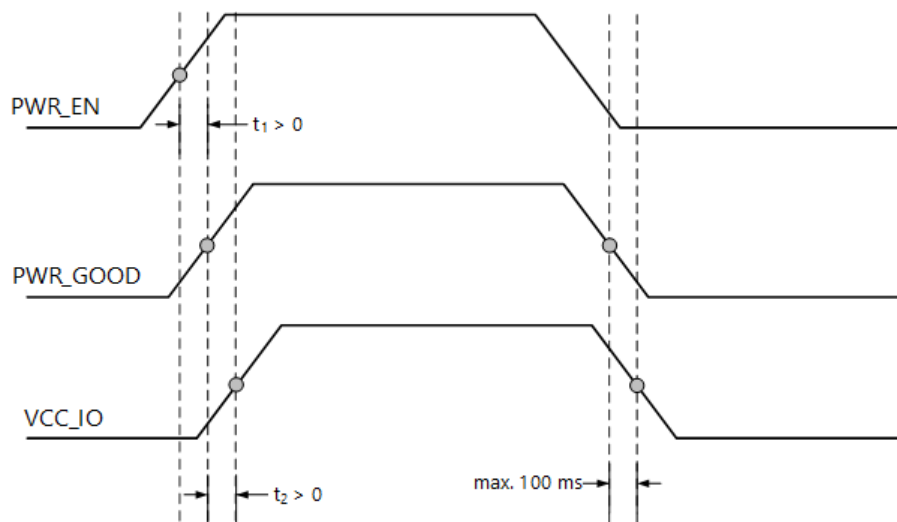


Figure 10: Power-Up Sequence - VCC_IO in Relation with PWR_GOOD and PWR_EN Signals

⁴Only discrete values are allowed. Refer to Zynq UltraScale+ MPSoC Data Sheet: DC and AC Switching Characteristics [30] for details.

⁵For HD I/O banks generic supply names are used. Refer to Section 3.8.4 for details on I/O banks connectivity and supplies.

⁶For voltages of 3.3 V for VCC_IO_BN and VCC_IO_BO the tolerance range is -5% to +3%.

NOTICE



Damage to the device due to unsuitable voltage

Unsuitable voltages may damage the MPSoC device as well as other devices on the Mercury+ XU8 SoC module.

- Only use VCC_IO voltages compliant with the assembled MPSoC device.

NOTICE



Damage to the device due to floating VCC_IO pins

Floating VCC_IO pins reduce ESD protection.

- Do not leave any VCC_IO pin floating.

⚠ CAUTION



Injury due to uncontrolled device

If an I/O is connected to an external device, violating the power sequence or leaving the corresponding VCC_IO pin floating will leave the pin in an undefined state. This can lead to any behavior of the devices attached to this pin and, potentially, to damage or injuries.

- Follow the power sequence diagram shown in Figure 10. This ensures that the I/Os are tri-stated at power-on and power-off.
- Do not leave VCC_IO pins floating.

On module connector C there are no VCC_IO pins available, as the signals routed to this connector belong to FPGA banks that are powered by fixed voltages generated on the module. Note that the VCC_IO pins on connector C are used on other Enclustra modules. For compatibility purposes it is acceptable to power these pins even if they are not used on the Mercury+ XU8 SoC module.

The Mercury+ XU8 SoC module may be used in combination with base boards having only two module connectors.

3.8.6 Signal Terminations

Differential Inputs

Internal differential termination is not supported for the HD pins. All differential signal pairs from both HD banks may optionally be equipped with 100 Ω differential termination resistors on the module.

The resistor identifiers for each differential input pair can be retrieved from the Mercury+ XU8 SoC Module User Schematic [5].

Single-Ended Outputs

There are no series termination resistors on the Mercury+ XU8 SoC module for single-ended outputs. If required, series termination resistors may be assembled on the base board (close to the module pins).

3.8.7 Multiplexed I/O (MIO) Pins

Details on the MIO/EMIO terminology are available in the Zynq UltraScale+ Device Technical Reference Manual [26].

Some of the MIO pins on the Mercury+ XU8 SoC module are connected to on-board peripherals, while others are available as GPIOs. The suggested functions below are for reference only. Always verify your MIO pinout with the AMD device handbook.

Table 11 gives an overview over the MIO pin connections on the Mercury+ XU8 SoC module. Only the pins marked with “user functionality” are available on the module connector.

MIO Pins	Function(s)	Connection(s)
[0:5]	QSPI flash	QSPI flash
[6]	QSPI feedback clock	_7
[7:9]	Unused	–
[10:11]	I2C	On-board I2C bus and module connector via level shifter
[12]	I2C interrupt	On-board I2C bus
[13:22]	eMMC flash	eMMC flash
[23]	USB PHY 1 reset	USB 2.0 PHY 1
[24:25]	LED0#, LED1#	On-board LEDs
[26:29,31:37]	Ethernet 0	Gigabit Ethernet PHY 0
[30]	Ethernet 0 PCIe block PERST# signal ⁸	Gigabit Ethernet PHY 0 Module connector via series resistor
[38]	UART RX ⁹ User functionality	Module connector
[39]	UART TX ⁹ User functionality	Module connector
[40:41,43:44]	User functionality	Module connector
[42]	PCIe block PERST# signal ⁸ User functionality	Module connector
[45:51]	SD card/user functionality	Module connector
[52:63]	USB 0	USB 2.0 PHY 0
[64:75]	Ethernet 1 USB 1	Gigabit Ethernet PHY 1 USB 2.0 PHY 1
[76:77]	Ethernet MDIO	Gigabit Ethernet PHY 1 and PHY 0 via level shifter

Table 11: MIO Pins Connections Overview

⁷This pin is intentionally left unconnected to allow enabling the QSPI “Feedback Clk” and achieving QSPI transfer speeds greater than 40 MHz. Refer to the Zynq UltraScale+ Device Technical Reference Manual [26] for more information.

⁸Used for PCIe PERST# connection implementation. Refer to Section 3.8.2 for details.

⁹UART RX is an MPSoC input; UART TX is an MPSoC output.

3.8.8 Analog Inputs

The Zynq UltraScale+ MPSoC devices contain a system monitor in the PL and an additional system monitor block in the PS. These are used to sample analog inputs and to collect information on the internal voltages and temperatures.

The system monitor block in the PL provides a 10-bit ADC, which supports up to 17 external analog lines (1 dedicated differential input, 16 auxiliary differential inputs). The auxiliary analog lines of the MPSoC device are available on the module connector. These I/Os have the abbreviation "AD" followed by the ADC channel in the signal name. The ADC lines are always used differentially. For single-ended applications, the *_N line must be connected to ground. The dedicated channel is not available on the module connector.

The analog input signals can be connected to any normal I/O FPGA bank, provided that all analog pins belong to the same bank. Note that the HD I/O banks have a limited number of analog inputs and they must be connected directly to the SYSMONE4 primitive instead of to the AMD System Management Wizard IP core.

For detailed information on the ADC and system monitor, refer to the UltraScale Architecture System Monitor document [28], Zynq UltraScale+ Device Technical Reference Manual [26] and System Management Wizard Product Guide [29].

Table 12 presents the ADC Parameters for the PL System Monitor (SYSMON). The PS System Monitor is only used for monitoring the on-chip power supply voltages and die temperature.

Parameter	Value (PL SYSMON)
VCC_ADC	1.8 V
VREF_ADC	Internal
ADC Range	0 – 1 V
Sampling Rate per ADC	0.2 MSPS
Total number of channels available on the module connector	16 (only auxiliary inputs)

Table 12: System Monitor (PL) Parameters

3.9 Multi-Gigabit Transceiver (MGT)

There are two types of multi-gigabit transceivers available on the Mercury+ XU8 SoC module: GTH transceivers (connected to the PL) and GTR transceivers (connected to the PS).

Tip

For optimal performance of high-speed interfaces, for example, PCIe, use redrivers on the base board.

Tip

The maximum data rate on the transceivers on the Mercury+ XU8 SoC module depends on the routing path for these signals. When using transceivers at high performance rates, ensure adequate signal integrity over the full signal path.

NOTICE



Damage to the transceivers

No AC coupling capacitors are placed on the Mercury+ XU8 SoC module on the transceivers.

- If required by your application, ensure that capacitors are mounted on the base board, close to the module pins.

GTH Transceivers

The GTH banks are numbered differently depending on the MPSoC device assembled on the module. Table 13 presents the mapping between the GTH generic bank letters and the device-specific bank numbers.

Device	Bank			
	A	B	C	D
ZU4	223	224	225	226
ZU5				
ZU7	224	225	226	227

Table 13: Mapping Between the Generic GTH Bank Letters and the Device-Specific GTH Bank Numbers

There are 16 GTH MGTs available on the Mercury+ XU8 SoC module organized in four FPGA banks. Table 14 describes the connections.

The naming convention for the GTH MGT I/Os is:

MGT_B<BANK_LETTER>_<FUNCTION>_<PACKAGE_PIN>_<POLARITY>.

For example, MGT_BB_TX2_L3_N is located on pin L3 of MGT I/O bank B, it is a transmit pin and it has negative polarity.

Signal Name	Signal Description	Pairs	I/O Bank
MGT_BA_RX<...>	MGT receivers	4	A
MGT_BA_TX<...>	MGT transmitters	4	
MGT_BA_REFCLK<...>	MGT reference input clocks	2	
MGT_BB_RX<...>	MGT receivers	4	B
MGT_BB_TX<...>	MGT transmitters	4	
MGT_BB_REFCLK<...>	MGT reference input clocks	2	
MGT_BC_RX<...>	MGT receivers	4	C
MGT_BC_TX<...>	MGT transmitters	4	
MGT_BC_REFCLK<...>	MGT reference input clocks	2	
MGT_BD_RX<...>	MGT receivers	4	D
MGT_BD_TX<...>	MGT transmitters	4	
MGT_BD_REFCLK<...>	MGT reference input clocks	2	
Total		40	

Table 14: MGT Pairs

Twelve of the GTH pairs and six corresponding clocks are routed to module connector C, while four GTH pairs and two reference input clock differential pairs are routed to module connector B.

The GTH MGTs on the MPSoC device support data rates of 12.5 Gbit/s on speed grade 1 devices and of 15 Gbit/s on the other devices.

The MPSoC devices assembled on the Mercury+ XU8 SoC module can support up to two integrated PCIe Gen3 $\times 16$ interfaces on the PL side, implemented using GTH transceivers. Simultaneous usage of these interfaces is limited to the available hardware resources (number of transceivers and lane mapping).

GTR Transceivers

There are four GTR MGT pairs and two reference input clock differential pairs on the Mercury+ XU8 SoC module connected to I/O bank 505. These are routed to module connector B.

The naming convention for the GTR MGT I/Os is:
MGTPS_<FUNCTION>_<PACKAGE_PIN>_<POLARITY>.

For example, MGTPS_RX2_H28_N is located on pin H28 of PS GTR bank (bank 505), it is a receive pin and it has negative polarity.

All Mercury+ XU8 SoC module variants support the implementation of a PCIe Gen2 $\times 4$ interface.

When the PCIe hard block is used, it is not possible to use the Ethernet 0 interface. Ethernet PHY 0 is connected to ETH 0 controller from the PS I/O bank 501. One of the Ethernet TX data signals is shared with the PCIe reset signal (PERST#). Refer to Sections 3.8.2 and 3.8.7 for details on the PERST# connection.

The GTR pairs support data rates of 6 Gbit/s and can be used for the implementation of several interfaces such as PCIe Gen2 ×4, USB 3.0, DisplayPort, SATA, or Ethernet SGMII. Refer to the Zynq UltraScale+ Device Technical Reference Manual [26] and to the Zynq UltraScale+ MPSoC Data Sheet: Overview [31] for details.

A 100 MHz LVDS oscillator and a 27 MHz CMOS oscillator provide reference clock inputs to the PS GTR bank 505. Refer to Section 3.11 for details.

3.10 Power

3.10.1 Power Generation Overview

The Mercury+ XU8 SoC module uses a 5 to 15 V DC power input for generating the on-board supply voltages. Some of these voltages are accessible on the module connector. Table 15 describes the power supplies generated on the module.

Generated Supply Name	Voltage Value	Rated Current	Source Supply Name	Shut down via PWR_EN	Influences PWR_GOOD
VCC_VTT	$\frac{1}{2} \times VCC_1V2$	±2 A	VCC_3V3	Yes	Yes
VCC_INT	0.72 V/0.85 V/0.9 V (PL core supply)	35 A	VCC_MOD	Yes	Yes
VCC_PSINT	0.85 V/0.9 V (PS core supply)	6 A	VCC_MOD	Yes	Yes
VCC_0V85 ¹⁰	0.85 V (GTR transceiver supply)	0.5 A	VCC_1V2	Yes	No
VCC_0V9	0.9 V	6 A	VCC_MOD	Yes	Yes
VCC_1V2	1.2 V	6 A	VCC_MOD	Yes	Yes
VCC_BAT_FPGA	1.2 V	10 mA	VCC_BAT	No	No
VCC_1V8	1.8 V	3 A	VCC_MOD	Yes	Yes
VCC_2V5	2.5 V	0.5 A	VCC_3V3	Yes ¹¹	No
VCC_3V3	3.3 V	6 A	VCC_MOD	No	Yes
VCC_5V0	5.0 V	0.15 A	VCC_MOD	No	No

Table 15: Generated Power Supplies

In the standard configuration the PL core supply is 0.85 V. For custom configurations in which a speed grade -3E MPSoC device is assembled, an assembly variant is available to switch the PL core operating voltage to 0.9 V. Similarly, in situations in which a speed grade -2LE or -1LI device is used, an assembly

¹⁰An LDO is used to generate the GTR transceiver supply, when a -1LI, -2LE, or -3E speed grade MPSoC device is used. For the other speed grades, VCC_INT is used.

¹¹On modules revision 1.1, the 2.5 V supply is not powered off by the PWR_EN signal. If this voltage is used to supply VCC_IO pins, power sequencing on the base board is required.

variant is available to switch the PL core operating voltage to 0.72 V.

In the standard configuration the PS core supply is 0.85 V. For custom configurations in which a speed grade -3E MPSoC device is assembled, an assembly variant is available to switch the PS core operating voltage to 0.9 V.

Refer to the Mercury Mars Module Pin Connection Guidelines [10] for general rules on the power pins.

3.10.2 Power Enable / Power Good

The Mercury+ XU8 SoC module provides a power enable input on the module connector. This input may be used to shut down the module's internal supply voltages when required. The list of supply voltages that can be disabled via PWR_EN signal is provided in Section 3.10.1.

The PWR_EN input is pulled to VCC_3V3 on the Mercury+ XU8 SoC module with a 4.7 k Ω resistor¹². The PWR_GOOD signal is pulled to VCC_3V3 on the Mercury+ XU8 SoC module with a 4.7 k Ω resistor¹².

PWR_GOOD is an open collector signal and must not be used to drive a load directly. This signal is pulled to ground if the onboard power converters fail or if the module is disabled via PWR_EN. The list of converters that influence the state of the PWR_GOOD signal is provided in Section 3.10.1.

The role of PWR_GOOD and PWR_EN on the VCC_IO power sequence is presented in Section 3.8.5.

NOTICE



Damage to the device due to unsuitable voltage

Applying unsuitable voltage to the power enable or power good pins can damage the Mercury+ XU8 SoC module.

- Do not actively drive the power enable or power good pins to anything other than ground.
- Do not pull these pins up to a voltage level higher than 3.3 V.

Signal Name	Module Connector Pin	Comment
PWR_EN	A-10	Floating/3.3 V: Module power enabled Driven low: Module power disabled
PWR_GOOD	A-12	0 V: Module supply not ok 3.3 V: Module supply ok

Table 16: Module Power Status and Control Pins

3.10.3 Voltage Supply Inputs

Table 17 describes the power supply inputs on the Mercury+ XU8 SoC module. The VCC voltages used as supplies for the I/O banks are described in Section 3.8.5.

¹²Prior to revision 3.0, a 10 k Ω resistor was used.

Supply Name	Module Conn. Pins	Voltage	Description
VCC_MOD	A-1, 2, 3, 4, 5, 6, 7, 8, 9, 11	5 – 15 V	Supply for on-module generated power supplies. The 2.5 V supply is generated from the 3.3 V supply. The input current is rated at 3 A (0.3 A per connector pin).
VCC_BAT	A-168	2.7 – 3.6 V	Supply for the battery voltage for MPSoC battery-backed RAM and battery-backed RTC.

Table 17: Voltage Supply Inputs

3.10.4 Voltage Supply Outputs

Table 18 presents the supply voltages generated on the Mercury+ XU8 SoC module, that are available on the module connector.

Supply Name	Module Connector Pins	Voltage	Typical Available Current ¹³	Comment
VCC_3V3	A-26, 29, 50, 86 B-55, 79, 115, 127, 152, 155 C-96, 103, 136, 143	3.3 V $\pm$ 5%	4 A (and max 0.3 A per pin)	Always active
VCC_2V5	A-53, 62, 65, 89	2.5 V $\pm$ 5%	0.25 A	Controlled by PWR_EN ¹⁴
VCC_1V8	B-52, 76, 108, 128 C-83, 123, 165	1.8 V $\pm$ 5%	1.5 A	Controlled by PWR_EN

Table 18: Voltage Supply Outputs

NOTICE



Damage to the device due to unsuitable usage of the output pins

- Do not connect any power supply to the voltage supply outputs.
- Do not short circuit any of the voltage supply outputs to ground.

3.10.5 Power Consumption

The power consumption of any MPSoC device strongly depends on the application (on the configured bitstream and I/O activity).

¹³The maximum available output current depends on your design. See Sections 3.10.1 and 3.10.5 for details.

¹⁴On module revision 1.1, the 2.5 V supply is not powered off by the PWR_EN signal. If this voltage is used to supply VCC_IO pins, power sequencing on the base board is required.

To estimate the power consumption of your design, use the power estimation tool provided by AMD for the corresponding device family, available on the AMD website.

3.10.6 Heat Dissipation

High performance devices like the AMD Zynq UltraScale+ MPSoC need cooling in most applications. Always make sure the MPSoC is adequately cooled.

For Mercury modules an Enclustra heat sink kit is available for purchase along with the product. It represents an optimal solution to cool the Mercury+ XU8 SoC module. The heat sink body is low profile and usually covers the whole module surface. The kit comes with a gap pad for the MPSoC device, a fan and required mounting material to attach the heat sink to the module PCB and base board PCB. With additional user configured gap pads, it is possible to cool other components on the board as well.

Alternatively, if the Enclustra heat sink does not match the application requirements, a third-party heat sink body (ATS) and an additional gap pad (t-Global) may be used. The Enclustra heat sink kit already contains all necessary items for cooling the module (heat sink body, gap pad, fan, mounting material).

Table 19 lists the heat sink and thermal gap pad part numbers that are compatible with the Mercury+ XU8 SoC module. Details on the Mercury heat sink kit can be found in the Mercury Heat Sink Kits User Manual [21].

Product Name	Package Name	Enclustra	ATS	t-Global
		Heat Sink	Heat Sink	Thermal Gap Pad
Mercury+ XU8	FBVB900 [27]	ACC-HS4-Set	ATS-52310G-C1-R0	TG-A6200-30-30-1

Table 19: Heat Sink Characteristics

Tip

Adhesive heat sinks are only recommended for prototyping purposes. When the module is used in environments subject to vibrations, additional mechanical fixation is recommended.

NOTICE



Damage to the device due to overheating

Depending on the user application, the Mercury+ XU8 SoC module may consume more power than can be dissipated without additional cooling measures.

- Ensure that the MPSoC is always adequately cooled by installing a heat sink and/or providing air flow.

3.10.7 Voltage Monitoring

Several pins on the module connector on the Mercury+ XU8 SoC module are marked as VMON. These are voltage monitoring outputs that are used in the production test for measuring some of the on-board voltages. It is not allowed to draw power from the voltage monitoring outputs.

Starting at revision 3, the VMON pins changed to increase the test coverage in the production test. The voltage monitoring pins on the Mercury+ XU8 SoC module are listed in Table 20 for product models up to revision 2.2 and in Table 21 for product models starting at revision 3.0.

Tip

The voltage monitoring outputs are for Enclustra-use only. Pinout changes may be applied between revisions.

Signal Name	Mod. Conn. Pin	Assembly Variant	Connection	Description
VMON_INT	A-102	All	VCC_INT	PL core voltage
VMON_VTT_VBAT	B-8	Default	VCC_VTT	DDR termination voltage
		Custom	VCC_VTT	MPSoC battery voltage
VMON_PSINT	B-168	All	VCC_PSINT	PS core voltage
VMON_0V9	B-167	All	VCC_0V9	0.9 V on-board voltage
VMON_1V2 ¹⁵	C-8	All	VCC_1V2	1.2 V on-board voltage

Table 20: Voltage Monitoring Outputs, up to Revision 2.2

Signal Name	Mod. Conn. Pin	Assembly Variant	Connection	Description
VMON_5V0	A-102	Default	$\frac{2}{5} \times VCC_5V0$	5 V on-board voltage
		Custom	VCC_INT	PL core voltage
VMON_VTT	B-8	All	VCC_VTT	VTT on-board voltage
VMON_0V9	B-167	Default	VCC_0V9	0.9 V on-board voltage
		Custom	VCC_0V85	0.85 V on-board voltage
VMON_1V2	B-168	Default	VCC_1V2	1.2 V on-board voltage
		Custom	VCC_PSINT	PS core voltage
VMON_BAT_FPGA	C-8	Default	–	Not connected
		Custom	VCC_BAT_FPGA	MPSoC battery voltage

Table 21: Voltage Monitoring Outputs, Revision 3.0 and Higher

¹⁵Voltage monitoring output available on the module connector starting with revision 2 modules.

3.11 Clock Generation

A 33.33 MHz oscillator is used for the Mercury+ XU8 SoC module clock generation. The 33.33 MHz clock is fed to the PS. A 100 MHz LVDS oscillator is connected to FPGA bank 65 and can serve as a reference for the PLL used to generate the clocks required for the PL DDR interface. The signal is terminated with a 100 Ω parallel resistor close to the FPGA pins. An additional 100 MHz clock is used as a reference clock input for PS GTR bank 505.

A 27 MHz CMOS oscillator provide a reference clock input to the PS GTR bank 505. A 24 MHz clock and a 25 MHz clock are used for the USB PHYs and Ethernet PHYs respectively. The crystal pads for the MPSoC RTC are connected to a 32.768 kHz oscillator on the Mercury+ XU8 SoC module.

Table 22 describes the clock connections to the MPSoC device.

Signal Name	Frequency	MPSoC Pin	MPSoC Pin Name
CLK33	33.33 MHz	P19	PS_REF_CLK
GTR_CLK27_P	27 MHz	H23	PS_MGTREFCLK3P_505
GTR_CLK27_N		H24	PS_MGTREFCLK3N_505
GTR_CLK100_P	100 MHz	K23	PS_MGTREFCLK2P_505
GTR_CLK100_N		K24	PS_MGTREFCLK2N_505
CLK100_P	100 MHz	AH6	IO_L13P_T2L_N0_GC_QBC_65
CLK100_N		AJ6	IO_L13N_T2L_N1_GC_QBC_65
PS_PADI	32.768 kHz	M21	PS_PADI (crystal pad input for MPSoC built-in RTC)
PS_PADO		N21	PS_PADO (crystal pad output for MPSoC built-in RTC)

Table 22: Module Clock Resources

3.12 Reset

The power-on reset signal (POR) and the PS system reset signal (SRST) of the MPSoC device are available on the module connector.

Pulling PS_POR# low resets the MPSoC device, the Ethernet and the USB PHYs, and the QSPI and eMMC flash devices. Refer to the Mercury Mars Module Pin Connection Guidelines [10] for general rules regarding the connection of reset pins.

Pulling PS_SRST# low resets the MPSoC device and enables the connection between QSPI flash and module connector, allowing the flash to be programmed from an external SPI master.

For details on the functions of the PS_POR_B and PS_SRST_B signals refer to the Zynq UltraScale+ Device Technical Reference Manual [26].

Table 23 presents the available reset signals. Both signals, PS_POR# and PS_SRST#, have on-board 4.7 k Ω pull-up resistors¹⁶ to VCC_CFG_MIO. For on-board devices using 1.8 V signaling, a PS_POR# low voltage variant is generated (PS_POR#_LV). PS_POR# is automatically asserted if PWR_GOOD is low.

¹⁶Prior to revision 3.0, 10 k Ω resistors were used.

Signal Name	Connector Pin	MPSoC Pin	MPSoC Pin Name	Description
PS_POR#	A-132	N19	PS_POR_B	Power-on reset
PS_SRST#	A-124	P20	PS_SRST_B	System reset

Table 23: Reset Resources

3.13 LEDs

There are three active-low user LEDs on the Mercury+ XU8 SoC module. Two of them are connected to the PS and one connected to the PL.

Signal Name	MPSoC Pin	MPSoC Pin Name	Comment
PS_LED0#	A18	MIO[24]	User function/active-low
PS_LED1#	B18	MIO[25]	User function/active-low
PL_LED2#	AF13	–	User function/active-low

Table 24: User LEDs

The module is also equipped with two status LEDs, which offer details on the configuration process for debugging purposes.

Signal Name	MPSoC Pin	MPSoC Pin Name	Comment
PS_ERROR	R22	PS_ERROR_OUT	Refer to Zynq UltraScale+ Device Technical Reference Manual [26]
PS_STATUS	R20	PS_ERROR_STATUS	Refer to Zynq UltraScale+ Device Technical Reference Manual [26]

Table 25: Status LEDs

3.14 DDR4 SDRAM (PS)

There are two DDR4 SDRAM channels on the Mercury+ XU8 SoC module: one attached directly to the PS side (which is available only as a shared resource to the PL side) and one attached directly to the PL side.

The DDR4 SDRAM connected to the PS is mapped to I/O bank 504. The memory configuration on the Mercury+ XU8 SoC module supports ECC error detection and correction. The correction code type used is single bit error correction and double bit error detection (SEC-DED).

Five 16-bit memory chips are used to build an 72-bit wide memory (8 bits are unused): 64 bits for data and 8 bits for ECC.

The maximum memory bandwidth on the Mercury+ XU8 SoC module is:
 $2'400 \text{ Mbit/s} \times 64 \text{ bit} = 19'200 \text{ MB/s}$

3.14.1 DDR4 SDRAM Characteristics

Table 26 describes the memory availability and configuration on the Mercury+ XU8 SoC module.

Module	Density	Configuration
ME-XU8-D11E	4 Gbit	256 M × 16 bit
ME-XU8-D12E	8 Gbit	512 M × 16 bit
ME-XU8-D13E	16 Gbit	1 G × 16 bit

Table 26: DDR4 SDRAM (PS) Characteristics

3.14.2 Signal Description

Refer to the Mercury+ XU8 SoC Module FPGA Pinout Excel Sheet [4] for detailed information on the DDR4 SDRAM connections.

3.14.3 Termination

Tip

No external termination is implemented for the data signals on the Mercury+ XU8 SoC module. Enclustra strongly recommends enabling the on-die termination (ODT) feature of the assembled device.

3.14.4 Parameters

Table 27 shows the parameters of the PS DDR4 SDRAM to be set in the Vivado project such that it corresponds to the Mercury+ XU8 SoC Module Reference Design [2].

Parameter	Value
Requested device frequency	1'200 MHz
Memory type	DDR4
Effective DRAM bus width	64 bit
ECC	Enabled
Speed bin	DDR4 2400T
CAS latency	17 cycles
RAS to CAS delay	17 cycles
Precharge time	17 cycles
CAS write latency	12 cycles
tRC	46.16 ns
tRASmin	32 ns
tFAW	30 ns
Additive latency	0 cycle
DRAM IC bus width (per die)	16 bit
DRAM chip capacity	4'096 or 8'192 Mbit
Bank group address count	1 bit
Bank address count	2 bit
Row address count	15 – 16 bit
Column address count	10 bit

Table 27: DDR4 SDRAM (PS) Parameters

3.15 DDR4 SDRAM (PL)

The DDR4 SDRAM connected to the PL is mapped to I/O banks 64 and 65. The DDR bus width is 32-bit.

The DDR4 SDRAM memory controller on the MPSoC device supports speeds up to 2'666 Mbit/s (1'333 MHz), however the memories assembled on the Mercury+ XU8 SoC module are rated 2'400 Mbit/s (1'200 MHz).

The maximum PL memory bandwidth on the Mercury+ XU8 SoC module is:
 $2'400 \text{ Mbit/s} \times 32 \text{ bit} = 9'600 \text{ MB/s}$

Note that for MPSoC low power mode (at 0.72 V) the DDR speed is lower than mentioned above. For details, refer to the Zynq UltraScale+ MPSoC Data Sheet: DC and AC Switching Characteristics [30].

3.15.1 DDR4 SDRAM Characteristics

Table 28 describes the memory availability and configuration on the Mercury+ XU8 SoC module.

Module	Density	Configuration
ME-XU8-D11E	4 Gbit	256 M × 16 bit
ME-XU8-D12E	8 Gbit	512 M × 16 bit
ME-XU8-D13E	16 Gbit	1 G × 16 bit

Table 28: DDR4 SDRAM (PL) Characteristics

3.15.2 Signal Description

Refer to the Mercury+ XU8 SoC Module FPGA Pinout Excel Sheet [4] for detailed information on the DDR4 SDRAM connections.

3.15.3 Termination

Tip

No external termination is implemented for the data signals on the Mercury+ XU8 SoC module. Enclustra strongly recommends enabling the on-die termination (ODT) feature of the assembled device.

3.15.4 Parameters

Table 29 shows the parameters of the PL DDR4 SDRAM to be set in the Vivado project such that it corresponds to the Mercury+ XU8 SoC Module Reference Design [2].

Parameter	Value
Memory device interface speed	833 ps
Reference input clock speed	10'000 ps (100 MHz) ¹⁷
Memory part	MT40A256M16 / MT40A512M16 ¹⁸
Data width	32 bit
Data mask and DBI	DM NO DBI
CAS latency	17 cycles
CAS write latency	12 cycles

Table 29: DDR4 SDRAM (PL) Parameters

¹⁷An exact period of 10'000 ps may not be achievable. The clock speed closest to the desired frequency should be selected.

¹⁸The memory devices assembled on the module may not be available in Vivado. In this case, a similar memory part with compatible timing requirements should be selected.

3.16 QSPI Flash

The QSPI flash can be used as boot media and application code memory for the PS. In addition, the QSPI flash can be used to store the FPGA bitstream and other user data.

3.16.1 QSPI Flash Characteristics

Table 30 describes the memory availability and configuration on the Mercury+ XU8 SoC module.

As there is one QSPI flash chip assembled on the Mercury+ XU8 SoC module, type "single" must be selected when programming the flash from Vivado tools.

Part Number	Density	Manufacturer
S25FL512S	512 Mbit	Infineon (Spansion)

Table 30: QSPI Flash Characteristics

Tip

Different flash memory devices may be assembled in future revisions of the Mercury+ XU8 SoC module. Any flash memory with a different speed and temperature range fulfilling the requirements of the module variant may be used.

3.16.2 Signal Description

The QSPI flash is connected to the PS MIO pins 0 to 5. Some of these signals are available on the module connector, allowing the user to program the QSPI flash from an external source.

The reset of the QSPI flash is connected to the PS_POR#_LV power-on reset signal.

Refer to Section 4 for details on programming the flash memory.

Tip

For optimal signal integrity, avoid long traces when connecting the QSPI flash signals on the base board. Long traces or high capacitance may disturb the data communication between the MPSoC and the flash device.

3.16.3 Configuration

The QSPI flash supports up to 50 MHz operation for standard read. For fast, dual and quad read speed values, refer to the flash device datasheet. The "Feedback Clk" option on pin MIO6 must be enabled in the Zynq configuration for clock rates higher than 40 MHz.

Refer to Zynq UltraScale+ Device Technical Reference Manual [26] for details on booting from the QSPI flash.

Using the Write Register (WWR) command can corrupt the QSPI flash. This issue is described in more details in the Mercury+ XU8 SoC Module Known Issues and Changes [6].

3.17 eMMC Flash

The eMMC flash can be used as boot media and application code memory for the PS, or to store the FPGA bitstream and other user data.

3.17.1 eMMC Flash Characteristics

The Mercury+ XU8 SoC module is equipped with a 16 GB eMMC flash.

Tip

Different flash memory devices may be assembled in future revisions of the Mercury+ XU8 SoC module. Any flash memory with a different speed and temperature range fulfilling the requirements of the module variant may be used.

3.17.2 Signal Description

The eMMC flash signals are connected to the MIO pins 13 to 22 for 8-bit data transfer mode. The command signal has a 4.7 k Ω pull-up resistor to 1.8 V and the data lines have 47 k Ω pull-up resistors to 1.8 V.

3.18 SD Card

An SD card can be connected to the PS MIO pins 45 to 51. The corresponding MIO pins are available on the module connector. Information on SD card boot mode is available in Section 4.6.5.

External pull-ups are needed for SD card operation. Depending on the selected voltage for VCC_CFG_MIO, a level shifter to 3.3 V may be required (some level shifters also have built-in pull-ups).

For booting from an Ultra High Speed (UHS) SD card, an SD 3.0 compliant level shifter is required on the base board and VCC_CFG_MIO must be set to 1.8 V. Note that this boot mode has not been tested, but it may be supported in the future.

3.19 Dual Gigabit Ethernet

Two 10/100/1000 Mbit Ethernet PHYs are available on the Mercury+ XU8 SoC module, both connected to the PS via RGMII interfaces.

3.19.1 Ethernet PHY Characteristics

Table 31 describes the Ethernet PHY devices assembled on the Mercury+ XU8 SoC module.

Part Number	Manufacturer	Description
KSZ9031RX	Microchip (Micrel)	10/100/1000 Mbit

Table 31: Gigabit Ethernet PHY Characteristics

3.19.2 Signal Description

PHY 0 is connected to ETH 0 controller from the PS I/O bank 501. One of the Ethernet TX data signals is shared with the PCIe reset signal (PERST#). If the application requires a hard PCIe block configured as endpoint, the ETH 0 interface is not available. Refer to Section 3.8.2 for details on the PERST# connection.

Tip

Remember that the Gigabit Ethernet 0 interface is not available when the PCIe endpoint in the PS is used, because of the PERST# connection.

PHY 1 is connected to ETH 3 controller from the PS bank 502. The corresponding MIO signals (64-75) are shared between Ethernet PHY 1 and USB PHY 1, therefore only one of them can be used. By default the Ethernet connection is enabled.

Tip

Remember that the USB 1 and Gigabit Ethernet 1 interfaces cannot be used simultaneously.

USB1_RST#_ETH1_RST is pulled to ground via a 1 k Ω resistor. To release the USB PHY from reset, this signal must be driven high from MIO23. ETH1_RST# is pulled to 1.8 V via a 4.7 k Ω resistor¹⁹. If USB1_RST#_ETH1_RST signal is driven high from the PS, the Ethernet reset is connected to ground.

Both reset signals (for Ethernet and USB) are pulled to ground if the PS_POR# is active. Table 32 describes the behavior of the USB1/ETH1 selection circuit. The default selection is marked in bold.

Condition		Function	
PS_POR#	USB1_RST#_ETH1_RST (MIO23)	USB PHY 1	Ethernet PHY 1
0	–	In reset	In reset
1	0	In reset	Active
1	1	Active	In reset

Table 32: USB1/ETH1 Selection

The two Gigabit Ethernet PHYs have a shared MDIO interface and a shared interrupt line. The interrupt output of the Ethernet PHYs is connected to the I2C interrupt line, available on MIO pin 12.

3.19.3 External Connectivity

The Ethernet signal lines can be connected directly to the magnetics. Refer to the Mercury Mars Module Pin Connection Guidelines [10] for details regarding the connection of Ethernet signals.

3.19.4 MDIO Address

The MDIO interface is shared between the two Gigabit Ethernet PHYs. These can be configured using the corresponding address. The MDIO address assigned to PHY 0 is 3 and to PHY 1 is 7.

The MDIO signals are mapped to MIO pins 76 and 77 and they are routed directly to PHY 1 and via a level shifter to PHY 0.

3.19.5 PHY Configuration

The configuration of the Ethernet PHYs is bootstrapped when the PHYs are released from reset. Make sure all I/Os on the RGMII interface are initialized and all pull-up or pull-down resistors are disabled at that moment.

The bootstrap options of the Ethernet PHYs are set as indicated in Table 33.

¹⁹Prior to revision 3.0, 10 k Ω resistors were used.

Strap Input	Signal Value	Description
MODE[3-0]	1110	RGMII mode: advertise all capabilities (10/100/1000, half/full duplex) except 1000Base-T half duplex.
PHYAD[2-0]	011	PHY0: MDIO address 3
	111	PHY1: MDIO address 7
CLK125_EN	0	125 MHz clock output disabled
LED_MODE	1	Single LED mode

Table 33: Gigabit Ethernet PHYs Configuration - Bootstraps

For the Ethernet PHY configuration via the MDIO interface, the MDC clock frequency must not exceed 2 MHz.

The PHY is configured in single LED mode with active-low LEDs 1 and 2.

3.19.6 RGMII Delays Configuration

The two Ethernet PHYs are connected directly to hard MAC controllers present in the MPSoC device. In order to achieve the best sampling eye for the RX and TX data, it is recommended to adjust the pad skew delays as specified in Table 34. These values have been successfully tested on Enclustra side.

The delays can be adjusted by programming the RGMII pad skew registers of the Ethernet PHY. Refer to the PHY datasheet for details.

PHY Register Name	Register Value [binary]	Delay Value
RXD0-RXD3	0111	0 ps
RX_DV	0111	0 ps
RX_CLK	01111	0 ps
TXD0-TXD3	0111	0 ps
TX_EN	0111	0 ps
GTX_CLK	11110	900 ps

Table 34: Gigabit Ethernet PHY (PS) Configuration for KSZ9031 - RGMII Delays

For RX_CLK, the PHY itself uses an additional default delay of 1.2 ns.

3.20 USB 2.0

Two USB 2.0 PHYs are available on the Mercury+ XU8 SoC module, both connected to the PS to I/O bank 502. USB PHY 0 can be configured as host or device, while USB PHY 1 can be used only as host.

If USB on-the-go (OTG) functionality is required, an assembly variant is available where the module connector pins A-131 (VBUS_HPD) and A-133 (ID_HDM) are connected to the USB PHY 0 pins 22 (VBUS) and 23 (ID) instead of being connected to the second USB PHY (pins DM and DP). Contact Enclustra support if USB OTG is required for your application.

3.20.1 USB PHY Characteristics

Table 35 describes the USB PHYs device assembled on the Mercury+ XU8 SoC module.

Part Number	Manufacturer	Description
USB3320C	Microchip	USB 2.0 PHY

Table 35: USB 2.0 PHY Characteristics

3.20.2 Signal Description

The ULPI interface for the PHY 0 is connected to MIO pins 52 to 63 for use with the integrated USB controller.

The ULPI interface for the PHY 1 is connected to MIO pins 64-75. The MIO signals are shared between Ethernet PHY 1 and USB PHY 1, therefore only one of them can be used. By default the Ethernet connection is enabled. Refer to Section 3.19.2 for details on how to select Ethernet or USB mode.

Tip

Remember that the USB 1 and Gigabit Ethernet 1 interfaces cannot be used simultaneously.

3.21 USB 3.0

AMD Zynq UltraScale+ devices feature two built-in USB 3.0 controllers and PHYs, configurable as host or device. The PHY interface used by the USB 3.0 controller is PIPE3, supporting a 5 Gbit/s data rate in host or device modes. The interface of each USB 3.0 controller uses one of the PS GTR lanes.

A 100 MHz differential clock is available on the module and connected to PS_MGTREFCLK2 pins, to be used as a reference clock for the USB 3.0 interface. It is also possible to provide another reference clock from the base board to the MGTPS_REFCLK* pins.

Details on the built-in USB 2.0/3.0 controller and on the usage of the PS GTR lanes are available in the Zynq UltraScale+ Device Technical Reference Manual [26] and in the Zynq UltraScale+ MPSoC Data Sheet: Overview [31].

Figure 11 shows an example of a USB 3.0 implementation using the built-in AMD USB 3.0 interface and the USB 2.0 signals from the PHY, all routed to a USB 3.0 connector on the base board.

Tip

The USB 3.0 interface on the Mercury+ XU8 SoC module uses the GTR signal lines (MGTPS signals on module connector B), and not the USB_SSRX_P/N and USB_SSTX_P/N signal lines on module connector A.

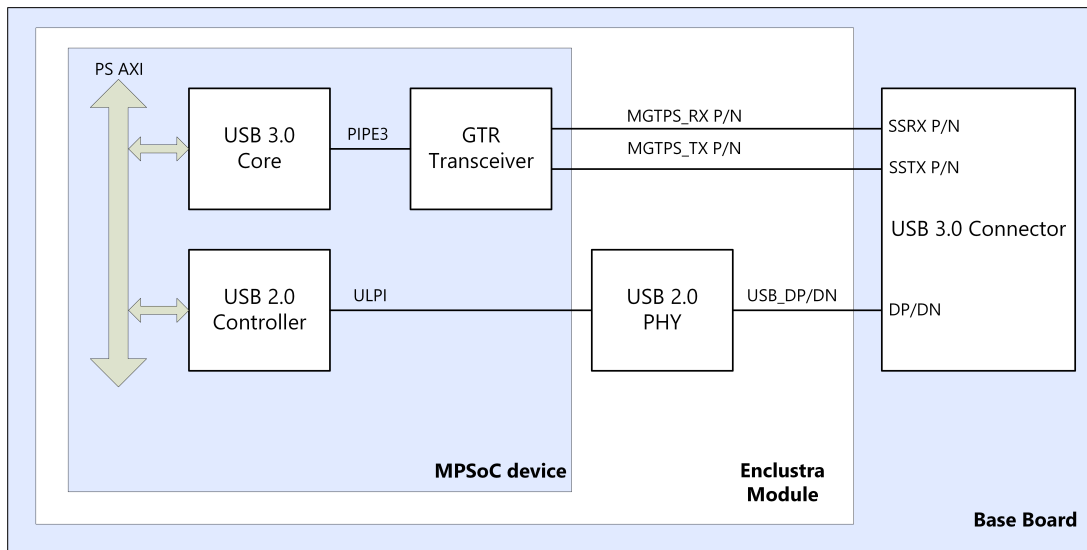


Figure 11: USB 3.0 Implementation Example

3.22 DisplayPort

AMD Zynq UltraScale+ devices feature two built-in DisplayPort controllers and PHYs, supporting up to two lanes at a 5.4 Gbit/s line rate. Each lane is represented by one of the PS GTR lines, available on the module connector.

A 27 MHz differential clock is available on the module and connected to PS_MGTREFCLK3 pins, to be used as a reference clock for the DisplayPort interface. It is also possible to provide another reference clock from the base board to the MGTPS_REFCLK* pins.

Details on the built-in DisplayPort controller and on the usage of the PS GTR lanes is available in the Zynq UltraScale+ Device Technical Reference Manual [26] and in the Zynq UltraScale+ MPSoC Data Sheet: Overview [31].

3.23 Real-Time Clock (RTC)

Zynq UltraScale+ devices include an internal real-time clock. The internal RTC can be accessed by the platform management unit (PMU). More information on the PMU is available in the Zynq UltraScale+ Device Technical Reference Manual [26].

The RTC crystal pad input and crystal pad output are connected on the Mercury+ XU8 SoC module to a 32.768 kHz oscillator.

A 1.2 V LDO is used to generate the battery voltage for the built-in RTC (supplied to VCC_PSBATT pin), based on the VCC_BAT voltage mapped to the module connector. This pin can be connected directly to a 3 V battery on the base board.

3.24 Module Information

The module information is stored on a persistent storage element. It contains the module type and serial number, as well as the Ethernet MAC address and other information. It is connected to the Management (MGMT) I2C bus. Refer to Section 5 for more information on the I2C communication.

3.24.1 Persistent Storage Element Characteristics

Table 36 describes the persistent storage element device assembled on the Mercury+ XU8 SoC module.

Part Number	Manufacturer	Assembly Variant
ATSHA204A-MAHDA-T	Microchip (Atmel)	Default
DS28CN01	Maxim	Custom

Table 36: Persistent Storage Element Characteristics

An example demonstrating how to read data from the persistent storage element is included in the Mercury+ XU8 SoC Module Reference Design [2].

4 Device Configuration

4.1 JTAG

The Zynq UltraScale+ devices include two separate JTAG controllers: the Zynq UltraScale+ TAP and the ARM DAP. The first one uses the PS dedicated JTAG pins and has access to both PS and PL and the second one uses the PS PJTAG pins and is used for loading programs, system test, and PS debug.

Details on JTAG and on system test and debug are available in the Zynq UltraScale+ Device Technical Reference Manual [26].

Certain AMD tool versions support QSPI flash programming via JTAG only when JTAG boot mode is used. Alternatively, the QSPI flash can be programmed in u-boot or Linux by the SPI controller in the PS or from an SPI external master.

4.1.1 JTAG on Module Connector

The PL and the PS JTAG interfaces are connected into one single chain available on the module connector. The PS_JTAG pins are used by the Zynq UltraScale+ TAP controller. The controller has full functionality only after the PS boot is complete. In order to enable the ARM DAP controller, special commands must be sent to the Zynq UltraScale+ TAP.

The MPSoC device and the flash devices can be configured via JTAG from AMD Vivado Hardware Manager or AMD Vitis. For this operation, the ARM DAP must be enabled.

Signal Name	Module Connector Pin	PS Dedicated Pin	Comment ²⁰
JTAG_TCK	A-123	PS_JTAG_TCK	4.7 kΩ pull-up to VCC_CFG_MIO
JTAG_TMS	A-119	PS_JTAG_TMS	4.7 kΩ pull-up to VCC_CFG_MIO
JTAG_TDI	A-117	PS_JTAG_TDI	4.7 kΩ pull-up to VCC_CFG_MIO
JTAG_TDO	A-121	PS_JTAG_TDO	4.7 kΩ pull-up to VCC_CFG_MIO

Table 37: JTAG Interface - PL and PS Access and Debug

4.1.2 External Connectivity

The JTAG signals can be connected to a JTAG connector on the base board. No pull-up/pull-down resistors are necessary. The VREF pin of the programmer must be connected to VCC_CFG_MIO.

It is recommended to add series termination resistors between the module and the JTAG header, close to the source. Enclustra also recommends adding a transient-voltage-suppression diode close to the JTAG connector to protect the MPSoC from damage due to ESD (Electrostatic Discharge). Refer to the Enclustra Module Pin Connection Guidelines for details on JTAG interface.

²⁰Prior to revision 3.0, 10 kΩ resistors were used instead of 4.7 kΩ resistors.

4.2 Configuration Signals

The PS of the MPSoC needs to be configured before the PL can be used. AMD Zynq devices need special boot images to boot from QSPI flash, eMMC flash or SD card. For more information, refer to the Zynq UltraScale+ Device Technical Reference Manual [26].

Table 38 describes the most important configuration pins and their location on the module connector. These signals allow the MPSoC to boot from QSPI flash, eMMC flash or SD card, and can be used to program the QSPI flash from an external master. Refer to Section 4.7.3 for details.

Signal Name	MPSoC Pin Name	Mod. Conn. Pin	Description	Comment ²¹
PS_DONE	PS_DONE	A-130	MPSoC device configuration done	1 k Ω pull-up to VCC_CFG_MIO
PS_POR#	PS_POR_B	A-132	MPSoC power-on reset	4.7 k Ω pull-up to VCC_CFG_MIO
PS_SRST#	PS_SRST_B	A-124	MPSoC system reset	4.7 k Ω pull-up to VCC_CFG_MIO
BOOT_MODE0	–	A-126	Boot mode selection	4.7 k Ω pull-up to VCC_CFG_MIO
BOOT_MODE1	–	A-112	Boot mode selection	4.7 k Ω pull-up to VCC_CFG_MIO

Table 38: MPSoC Configuration Pins

NOTICE



Damage to the device

- Only allow the signals PS_POR# and PS_SRST# to be driven low.
- Do not drive PS_POR# or PS_SRST# to a logic high level.
- Do not drive onto the PS_DONE pin on the base board.

4.3 Module Connector C Detection

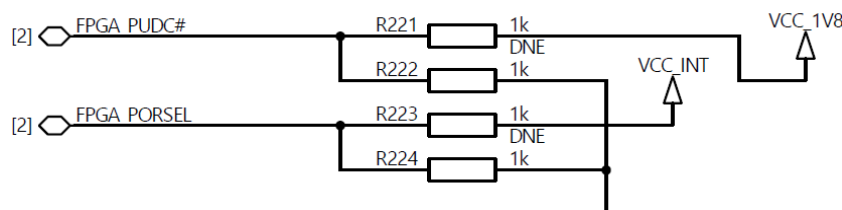
Signal C_PRSENT# (pin C167) is equipped with a 4.7 k Ω pull-up resistor to 3.3 V on the module. Since the VCC_IO pins on connector C are not used, C_PRSENT# does not influence the behavior of the module.

For compatibility with other Enclustra modules, it is recommended to connect C_PRSENT# to ground on the base board if the designed base board has three connectors.

²¹Prior to revision 3.0, 10 k Ω resistors were used instead of 4.7 k Ω resistors.

The Pull-Up During Configuration signal (PUDC) is pulled to ground on the module. As PUDC is an active-low signal, all FPGA I/Os will have the internal pull-up resistors enabled during device configuration.

Figure 12 illustrates the configuration of the I/O signals during power-up. Figure 13 indicates the location of the pull-up/pull-down resistors on the module PCB, lower right part on the bottom view drawing.



For details on the PUDC signal, refer to the Zynq UltraScale+ Device Technical Reference Manual [26].

The power-on reset delay override MPSoC signal (POR_OVERRIDE) is pulled to ground on the module, setting the PL power-on delay time to the default standard time.

If the application requires faster PL power-on delay time, this can be achieved by removing R224 component and by mounting R223.

Figure 12 illustrates the configuration of the POR_OVERRIDE signal. Figure 13 indicates the location of the pull-up/pull-down resistors on the module PCB, lower right part on the bottom view drawing.

For details on the POR_OVERRIDE signal, refer to the Zynq UltraScale+ Device Technical Reference Manual [26].

4.6 Boot Mode

4.6.1 Boot Mode Selection

The boot mode can be selected via two signals available on the module connector.

Table 39 describes the available boot modes on the Mercury+ XU8 SoC module.

Starting with revision 2, JTAG boot mode has been introduced to increase the usability with AMD tools, which may report issues when programming the on-board QSPI flash or when loading the FPGA bitstream in a non-JTAG boot mode.

BOOT MODE1	BOOT MODE0	Mode Straps [3:0]	Description	Comment
0	0	0110	Boot from eMMC flash	–
0	1	1110	Boot from SD card (with an external SD 3.0 compliant level shifter; only available when VCC_CFG_MIO is 1.8 V)	Not supported (may be supported in the future)
1	0	0010	Boot from QSPI flash	–
1	1	0101	Boot from SD card (default mode)	–
1	0	0000	JTAG boot mode	Available only starting with revision 2 modules in certain conditions (refer to Section 4.6.2 for details).

Table 39: Boot Modes

4.6.2 JTAG Boot Mode

Starting with revision 2, support for JTAG boot mode has been added to increase the usability of the module with AMD tools, for example for QSPI flash programming or FPGA bitstream loading.

Tip

JTAG boot mode is used explicitly for initial booting and is not required for the general JTAG mode used for programming, debugging, and in-system testing.

The following steps are required in order to boot the module in JTAG mode:

1. Set the boot mode selection signals for QSPI boot.
2. While powering-up the module, short-circuit R252 (see Figure 14). This allows to sample the MPSoC boot selection pins correctly for JTAG boot mode.

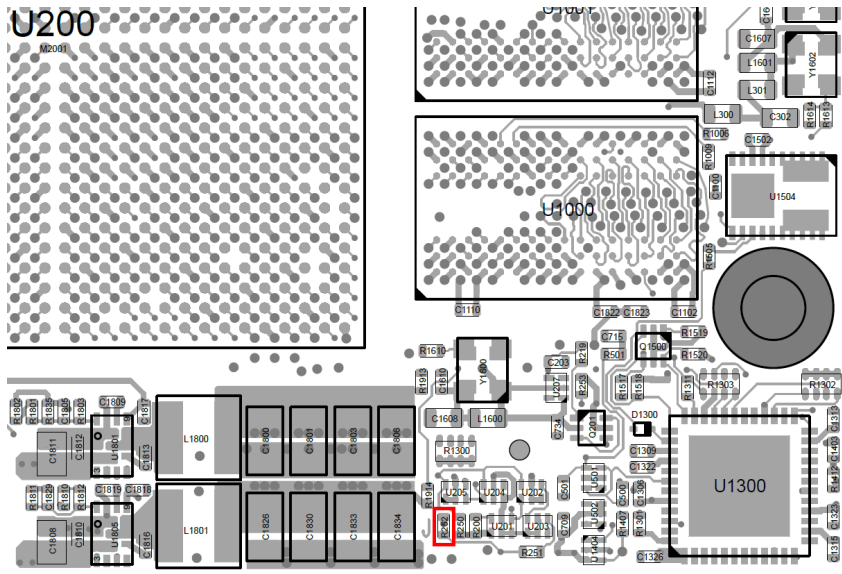


Figure 14: JTAG Boot Mode Resistor - Assembly Drawing Top View (lower right part)

4.6.3 eMMC Boot Mode

In the eMMC boot mode, the PS boots from the eMMC flash located on the module. The flash device is connected to the PS MIO pins 13 to 22 for 8-bit data transfer mode.

4.6.4 QSPI Boot Mode

In the QSPI boot mode, the PS boots from the QSPI flash located on the module. The flash device is connected to the PS MIO pins 0 to 5.

4.6.5 SD Card Boot Mode

In the SD card boot mode the PS boots from the SD card located on the base board. Two SD card boot modes are available on the Mercury+ XU8 SoC module, as described in Table 39. The SD boot mode with level shifter is currently not supported.

The SD boot mode with level shifter is used with Ultra High Speed (UHS) SD cards. The controller will start the communication at 3.3 V and afterwards it will command the card to drop from 3.3 V operation to 1.8 V operation. For this mode, an external SD 3.0 compliant level shifter is required. This boot mode may be supported in the future by Enclustra modules and base boards.

For the SD card boot mode, the following requirements must be met:

- The SD card must be connected to MIO pins 45 to 51.
- A Zynq boot image must be generated from an MPSoC design having the SDIO controller enabled.
- The boot image must be named "boot.bin" and then copied to the SD card.
- The SDIO controller must be fed with a reasonable clock frequency. Refer to the reference design for guidelines on SDIO settings.

For details on SD card boot, refer to the Zynq UltraScale+ Device Technical Reference Manual [26].

4.7 Flash Programming

4.7.1 eMMC Flash Programming

The eMMC flash can be formatted and/or programmed in u-boot or Linux, like a regular SD card. The boot image or independent partition files can be transmitted via Ethernet or copied from another storage device.

Certain AMD tool versions support eMMC flash programming via JTAG.

4.7.2 QSPI Flash Programming via JTAG

The AMD Vivado and Vitis software offer QSPI flash programming support via JTAG.

Certain AMD tools versions support QSPI flash programming via JTAG only when JTAG boot mode is used. For more information, refer to the Zynq UltraScale+ Device Technical Reference Manual [26]. Alternatively, the QSPI flash can be programmed in u-boot or Linux by the SPI controller in the PS or from an SPI external master.

4.7.3 QSPI Flash Programming from an External SPI Master

The signals of the QSPI flash are directly connected to the module connector for flash access, as shown in Table 40. As the flash signals are connected to the MPSoC device as well, the MPSoC device pins must be tri-stated while accessing the QSPI flash directly from an external device. This is ensured by pulling the PS_SRST# signal to ground followed by a pulse on PS_POR#, which puts the MPSoC device into reset state and tri-states all I/O pins. PS_SRST# must be low when PS_POR# is released and kept low until the flash programming has finished. Afterwards, all SPI lines and PS_SRST# must be tri-stated and another reset impulse must be applied to PS_POR#.

Signal Name	MPSoC Pin	Mod. Conn. Pin	Description	Comment
FLASH_CLK	MIO0	A-118	SPI CLK	4.7 k Ω pull-up to VCC_CFG_MIO
FLASH_DO	MIO1	A-122	SPI MISO	–
FLASH_DI	MIO4	A-114	SPI MOSI	4.7 k Ω pull-up to VCC_CFG_MIO
FLASH_CS#	MIO5	A-116	SPI CS#	4.7 k Ω pull-up to VCC_CFG_MIO

Table 40: QSPI Flash Signals for External Access

Figure 15 shows the signal diagrams corresponding to flash programming from an external master.

In addition, a non-QSPI boot mode must be used during QSPI flash programming, otherwise the MPSoC device will attempt to boot from the flash and will disturb the clock.

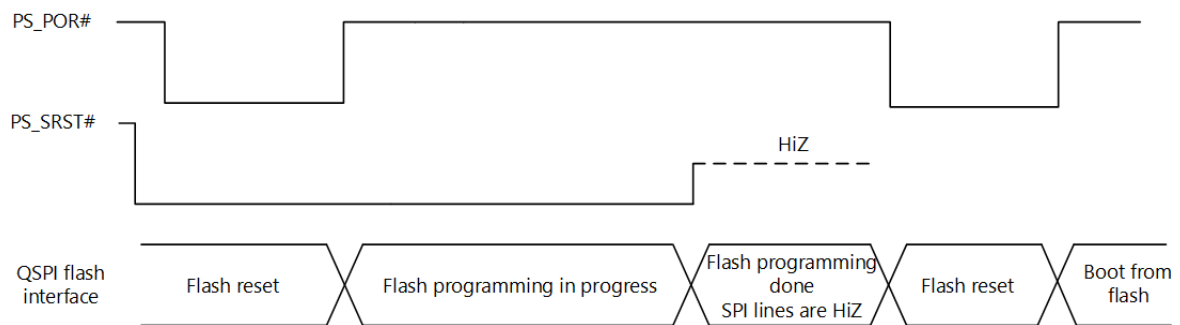


Figure 15: QSPI Flash Programming from an External SPI Master - Signal Diagrams

NOTICE



Damage to the device

The module can be damaged if the QSPI flash signals are driven simultaneously by the module and the base board.

- While accessing the QSPI flash from the module connector, put the MPSoC device into reset and select a non-QSPI boot mode.

4.8 Enclustra Module Configuration Tool

In combination with an Enclustra base board, the QSPI flash can be programmed using Enclustra Module Configuration Tool (MCT) [20]. For this method, a non-QSPI boot mode must be used during QSPI flash programming. The entire procedure is described in the reference design documentation.

The AMD Zynq devices do not support slave serial configuration, therefore only flash programming is supported by the Enclustra MCT for the Mercury+ XU8 SoC module.

5 I2C Communication

5.1 Overview

The I2C bus on the Mercury+ XU8 SoC module is connected to the MPSoC device and to the persistent storage element, and is available on the module connector. This allows external devices to read the module type and to connect more devices to the I2C bus.

The I2C clock frequency should not exceed 400 kHz.

Tip

Maximum I2C speed may be limited by the routing path and additional loads on the base board.

Tip

If the I2C traces on the base board are very long, 100 Ω series resistors should be added between the module and the I2C device on the base board.

5.2 Signal Description

Table 41 describes the signals of the I2C interface. The pins are connected to both PS and PL. All signals have on-board pull-up resistors to VCC_3V3.

All signals must be connected to open collector outputs and must not be driven high from any source. I2C_INT# is an input to the MPSoC and must not be driven from the MPSoC device.

Level shifters are used between the I2C bus and MPSoC pins, as I/O banks 500 and 64 are supplied with 1.8 V and 1.2 V respectively. Ensure that all pins are configured correctly and no pull-down resistors are enabled.

Signal Name	PS Pin Name	PL MPSoC Pin	Connector Pin	Comment
I2C_SDA	MIO11	AH13	A-113	2.2 k Ω pull-up to VCC_3V3
I2C_SCL	MIO10	AB13	A-111	2.2 k Ω pull-up to VCC_3V3
I2C_INT#	MIO12	–	A-115	4.7 k Ω pull-up to to VCC_3V3

Table 41: I2C Signal Description

5.3 I2C Address Map

Table 42 describes the addresses for several devices connected on I2C bus. For details on the characteristics of the persistent storage element, refer to Section 3.24.

Address (7-bit)	Description	Assembly Variant
0x5C	Persistent storage element	Custom
0x64	Persistent storage element	Default

Table 42: I2C Addresses

5.4 Module Information

The module information is stored on the persistent storage element. It includes the module serial number and configuration. An example demonstrating how to read the module information from the persistent storage element memory is included in the Mercury+ XU8 SoC module reference design.

Tip

Any attempt to write data to the persistent storage element causes the warranty to be rendered void.

5.4.1 Memory Map

Address	Length (bits)	Description
0x00	32	Module serial number
0x04	32	Module product information
0x08	40	Module configuration
0x0D	24	Reserved
0x10	48	Ethernet MAC address
0x16	48	Reserved
0x1C	32	Checksum (only for DS28CN01 type)

Table 43: Persistent Storage Element Sector 0 Memory Map

Module Serial Number

The module serial number is a unique 32-bit number that identifies the module. It is stored using big-endian byte order (MSB on the lowest address).

Module Product Information

This field indicates the type of module and hardware revision.

Module	Product Series	Reserved	Revision	Product Information
Mercury+ XU8 SoC module	0x0335	0x[XX]	0x[YY]	0x0335 [XX][YY]

Table 44: Product Information

Module Configuration

Addr.	Bits	Description	Min. Value	Max. Value	Comment
0x08	7-4	MPSoC type	0	3	Table 46
	3-0	MPSoC device speed grade	1	3	
0x09	7-6	Temperature range	0	2	Table 47
	5	Power grade	0 (Normal)	1 (Low power)	
	4-3	Gigabit Ethernet port count	0	2	
	2	RTC assembled	0 (No)	1 (Yes)	
	1-0	Reserved	–	–	
0x0A	7-2	Reserved	–	–	
	1-0	USB 2.0 port count	0	2	
0x0B	7-4	DDR4 ECC RAM (PS) size (GB)	0 (0 GB)	4 (8 GB)	Resolution = 1 GB
	3-0	DDR4 RAM (PL) size (GB)	0 (0 MB)	3 (4 GB)	Resolution = 1 GB
0x0C	7-4	eMMC flash size (GB)	0 (0 GB)	5 (16 GB)	Resolution = 1 GB
	3-0	QSPI flash memory size (MB)	0 (0 MB)	7 (64 MB)	Resolution = 1 MB

Table 45: Module Configuration

The memory sizes are defined as $\text{Resolution} \times 2^{(\text{Value}-1)}$, for example:

- DRAM = 0: none
- DRAM = 1: 1 GB
- DRAM = 2: 2 GB
- DRAM = 3: 4 GB

Table 46 shows the available MPSoC types.

Value	MPSoC Device Type
0	XCZU4CG
1	XCZU5EV
2	XCZU7EV
3	XCZU7EG

Table 46: MPSoC Device Types

Table 47 shows the available temperature ranges.

Value	Module Temperature Range
0	Commercial
1	Extended
2	Industrial

Table 47: Module Temperature Range

Ethernet MAC Address

The Ethernet MAC address is stored using big-endian byte order (MSB on the lowest address). Each module is assigned two sequential MAC addresses. Only the lower one is stored in the persistent storage element.

6 Operating Conditions

6.1 Absolute Maximum Ratings

Table 48 indicates the absolute maximum ratings for Mercury+ XU8 SoC module. The values given are for reference only. For details, refer to the Zynq UltraScale+ MPSoC Data Sheet: DC and AC Switching Characteristics [30].

Parameter	Description	Min.	Max.	Unit
VCC_MOD	Supply voltage relative to ground	-0.5	16	V
VCC_BAT	Supply voltage for MPSoC battery-backed RAM and battery-backed RTC	0.0	6.0	V
VCC_IO_BN VCC_IO_BO	I/O bank supply voltage relative to ground (V_{CCO})	-0.5	3.4	V
VCC_IO_B66	I/O bank supply voltage relative to ground (V_{CCO})	-0.5	2.0	V
VCC_CFG_MIO	I/O bank supply voltage relative to ground (V_{CCO_PSIO})	-0.5	3.63	V
IO_B[x]_<...>	I/O signal lines input voltage relative to ground (V_{IN})	-0.5	$V_{CCO}+0.5$	V
MGT_B[x]_<...>	PS I/O signal lines input voltage relative to ground (V_{PSIN})	-0.5	$V_{CCO_PSIO} + 0.55$	V

Table 48: Absolute Maximum Ratings

6.2 Recommended Operating Conditions

Table 49 indicates the recommended operating conditions for Mercury+ XU8 SoC module. The values given are for reference only. For details, refer to the Zynq UltraScale+ MPSoC Data Sheet: DC and AC Switching Characteristics [30].

Parameter	Description	Min.	Typ.	Max.	Unit
VCC_MOD	Supply voltage relative to ground	4.75	5.0 – 15.0	15.75	V
VCC_BAT	Supply voltage for MPSoC battery-backed RAM and battery-backed RTC	2.0	–	5.5	V
VCC_IO_B[x]	I/O bank supply voltage relative to ground (V_{CCO})	Refer to Section 3.8.5			
VCC_CFG_MIO	I/O bank supply voltage relative to ground (V_{CCO_PSIO})				
IO_B[x]_<...>	I/O signal lines input voltage relative to ground (V_{IN})	-0.2	–	$V_{CCO} + 0.2$	V
MGT_B[x]_<...>	PS I/O signal lines input voltage relative to ground (V_{PSIN})	-0.2	–	$V_{CCO_PSIO} + 0.2$	V
Power	Maximum module power consumption ²²	–	–	45	W
Temperature ²³	Temperature range for extended temperature modules (E)	0	–	+85	°C
	Temperature range for industrial modules (I)	-40	–	+85	°C

Table 49: Recommended Operating Conditions

NOTICE



Damage to the device due to overheating

Depending on the user application, the Mercury+ XU8 SoC module may consume more power than can be dissipated without additional cooling measures.

- Ensure that the MPSoC is always adequately cooled by installing a heat sink and/or providing air flow.

²²Sum of all power inputs at maximum rated current

²³The components used on the hardware are specified for the relevant temperature range. The user must provide adequate cooling in order to keep the temperature of the components within the specified range.

7 Ordering and Support

7.1 Ordering

Use the Enclustra online request/order form for ordering or requesting information:

<http://www.enclustra.com/en/order/>

7.2 Support

Follow the instructions on the Enclustra online support site:

<http://www.enclustra.com/en/support/>

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References

- [1] Enclustra General Business Conditions
<http://www.enclustra.com/gbc/>
- [2] Mercury+ XU8 SoC Module Reference Design
<https://github.com/enclustra>
- [3] Mercury+ XU8 SoC Module IO Net Length Excel Sheet
→ Ask Enclustra for details
- [4] Mercury+ XU8 SoC Module FPGA Pinout Excel Sheet
<https://www.enclustra.com/me-xu8-fpga-pinout>
- [5] Mercury+ XU8 SoC Module User Schematic
<https://www.enclustra.com/me-xu8-user-schematic>
- [6] Mercury+ XU8 SoC Module Known Issues and Changes
<https://www.enclustra.com/me-xu8-known-issues-and-changes>
- [7] Mercury+ XU8 SoC Module Footprint
<https://www.enclustra.com/me-xu8-footprint>
- [8] Mercury+ XU8 SoC Module 3D Model (PDF)
<https://www.enclustra.com/me-xu8-3d-pdf>
- [9] Mercury+ XU8 SoC Module 3D Model (STEP)
<https://www.enclustra.com/me-xu8-3d-step>
- [10] Mercury Mars Module Pin Connection Guidelines
→ Ask Enclustra for details
- [11] Mercury Master Pinout
→ Ask Enclustra for details
- [12] Hirose FX10 Series Product Website
<http://www.hirose.com/>
- [13] Mercury+ PE1 User Manual
<https://www.enclustra.com/me-pe1-user-manual>
- [14] Mercury+ ST1 User Manual
<https://www.enclustra.com/me-st1-user-manual>
- [15] Mercury+ PE3 User Manual
<https://www.enclustra.com/me-pe3-user-manual>
- [16] Enclustra Build Environment
<https://github.com/enclustra-bsp>
- [17] Enclustra Build Environment How-To Guide
<https://github.com/enclustra/EBEAppNote>
- [18] Petalinux BSP and Documentation
<https://github.com/enclustra/PetalinuxDocumentation>
- [19] Enclustra Yocto BSP Layer
<https://github.com/enclustra/meta-enclustra-amd>
- [20] Enclustra Module Configuration Tool
<https://www.enclustra.com/module-configuration-tool>
- [21] Mercury Heat Sink Kits User Manual
<https://www.enclustra.com/me-heat-sink-application-note>
- [22] Enclustra I2C Application Note
<https://github.com/enclustra/I2CAppNote>
- [23] Enclustra Gigabit Ethernet Application Note
<https://github.com/enclustra/GigabitEthernetAppNote>
- [24] Enclustra ZynqMP Video Application Note
<https://github.com/enclustra/ZynqMpVideoAppNote>
- [25] Enclustra Secure Boot Reference Design for Zynq Ultrascale+ MPSoC
<https://github.com/enclustra/ZynqMPSecureBootAppNote>
- [26] Zynq UltraScale+ Device Technical Reference Manual, UG1085, AMD Xilinx, 2025
- [27] Zynq UltraScale+ Device, Packaging and Pinouts Product Specification User Guide, UG1075, v1.13, AMD Xilinx, 2024

- [28] UltraScale Architecture System Monitor User Guide, UG580, AMD Xilinx, 2021
- [29] System Management Wizard v1.1 Product Guide, PG185, AMD Xilinx, 2014
- [30] Zynq UltraScale+ MPSoC Data Sheet: DC and AC Switching Characteristics, DS925, AMD Xilinx, 2023
- [31] Zynq UltraScale+ MPSoC Data Sheet: Overview, DS891, AMD Xilinx, 2025